



## POWER MANAGEMENT IC FOR LI-ION POWERED SYSTEMS

### FEATURES

- 1.2 A, 97% Efficient Step-Down Converter for System Voltage (VDCDC1)
- 1 A, Up to 95% Efficient Step-Down Converter for Memory Voltage (VDCDC2)
- 900 mA, 90% Efficient Step-Down Converter for Processor Core (VDCDC3)
- 30 mA LDO/Switch for Real Time Clock (VRTC)
- 2 × 200 mA General-Purpose LDO
- Dynamic Voltage Management for Processor Core
- Preselectable LDO Voltage Using Two Digital Input Pins
- Externally Adjustable Reset Delay Time
- Battery Backup Functionality
- Separate Enable Pins for Inductive Converters
- I<sup>2</sup>C™ Compatible Serial Interface
- 85-μA Quiescent Current
- Low Ripple PFM Mode
- Thermal Shutdown Protection
- 40-Pin 6 mm x 6 mm QFN Package

### APPLICATIONS

- PDA
- Cellular/Smart Phone
- Internet Audio Player
- Digital Still Camera
- Digital Radio Player
- Split Supply TMS320™ DSP Family and μP Solutions:  
OMAP™1610, OMAP1710, OMAP330, XScale  
Bulverde, Samsung ARM-Based Processors,  
etc.
- Intel® PXA270, etc.

### DESCRIPTION

The TPS65021 is an integrated Power Management IC for applications powered by one Li-Ion or Li-Polymer cell, and which require multiple power rails. The TPS65021 provides three highly efficient, step-down converters targeted at providing the core voltage, peripheral, I/O and memory rails in a processor based system. All three step-down converters enter a low-power mode at light load for maximum efficiency across the widest possible range of load currents. The TPS65021 also integrates two general-purpose 200 mA LDO voltage regulators, which are enabled with an external input pin. Each LDO operates with an input voltage range between 1.5 V and 6.5 V, allowing them to be supplied from one of the step-down converters or directly from the battery. The default output voltage of the LDOs can be digitally set to 4 different voltage combinations using the DEFLDO1 and DEFLDO2 pins. The serial interface can be used for dynamic voltage scaling, masking interrupts, or for dis/enabling and setting the LDO output voltages. The interface is compatible with the Fast/Standard mode I<sup>2</sup>C specification, allowing transfers at up to 400 kHz. The TPS65021 is available in a 40-pin (RHA) QFN package, and operates over a free-air temperature of -40°C to 85°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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I2C is a trademark of Philips Electronics.



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

## ORDERING INFORMATION

| T <sub>A</sub> | PACKAGE <sup>(1)</sup> | PART NUMBER <sup>(2)</sup> |
|----------------|------------------------|----------------------------|
| –40°C to 85°C  | 40 pin QFN (RHA)       | TPS65021RHA                |

- (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI Web site at [www.ti.com](http://www.ti.com).
- (2) The RHA package is available in tape and reel. Add the R suffix (TPS65021RHAR) to order quantities of 2500 parts per reel. Add the T suffix (TPS65021RHAT) to order quantities of 250 parts per reel.

## ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

|   | VALUE                        | UNIT |
|---|------------------------------|------|
| V <sub>I</sub> Input voltage range on all pins except AGND and PGND pins with respect to AGND | –0.3 to 7                    | V    |
| Current at VINDCDC1, L1, PGND1, VINDCDC2, L2, PGND2, VINDCDC3, L3, PGND3                      | 2000                         | mA   |
| Peak Current at all other pins  | 1000                         | mA   |
| Continuous total power dissipation  | See Dissipation Rating Table |      |
| T <sub>A</sub> Operating free-air temperature   | –40 to 85                    | °C   |
| T <sub>J</sub> Maximum junction temperature   | 125                          | °C   |
| T <sub>stg</sub> Storage temperature  | –65 to 150                   | °C   |

- (1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

## DISSIPATION RATINGS

| PACKAGE               | T <sub>A</sub> ≤ 25°C<br>POWER RATING | DERATING FACTOR<br>ABOVE T <sub>A</sub> = 25°C | T <sub>A</sub> = 70°C<br>POWER RATING | T <sub>A</sub> = 85°C<br>POWER RATING |
|-----------------------|---------------------------------------|--|---------------------------------------|---------------------------------------|
| RHA <sup>(1)(2)</sup> | 2.85 W                                | 28 mW/°C                                       | 1.57 W                                | 1.14 W                                |

- (1) The thermal resistance junction to ambient of the RHA package is 35°C/W measured on a high K board.
- (2) The thermal resistance junction to case (exposed pad) of the RHA package is 5°C/W.

## RECOMMENDED OPERATING CONDITIONS

over operating free-air temperature range (unless otherwise noted)

|                       |   | MIN | NOM | MAX       | UNIT |
|-----------------------|---|-----|-----|-----------|------|
| V <sub>CC</sub>       | Input voltage range step-down convertors (VINDCDC1, VINDCDC2, VINDCDC3)   | 2.5 |     | 6         | V    |
| V <sub>O</sub>        | Output voltage range for VDCDC1 step-down convertor <sup>(1)</sup>        | 0.6 |     | VINDCDC1  | V    |
|                       | Output voltage range for VDCDC2 (mem) step-down convertor <sup>(1)</sup>  | 0.6 |     | VINDCDC2  |      |
|                       | Output voltage range for VDCDC3 (core) step-down convertor <sup>(1)</sup> | 0.6 |     | VINDCDC3  |      |
| V <sub>I</sub>        | Input voltage range for LDOs (VINLDO1, VINLDO2)                           | 1.5 |     | 6.5       | V    |
| V <sub>O</sub>        | Output voltage range for LDOs (VLDO1, VLDO2)                              | 1   |     | VINLDO1-2 | V    |
| I <sub>O(DCDC2)</sub> | Output current at L1  |     |     | 1200      | mA   |
|                       | Inductor at L1 <sup>(2)</sup>   | 2.2 | 3.3 |           | μH   |
| C <sub>I(DCDC1)</sub> | Input Capacitor at VINDCDC1 <sup>(2)</sup>                                | 10  |     |           | μF   |
| C <sub>O(DCDC1)</sub> | Output Capacitor at VDCDC1 <sup>(2)</sup>                                 | 10  | 22  |           | μF   |
| I <sub>O(DCDC2)</sub> | Output current at L2  |     |     | 1000      | mA   |
|                       | Inductor at L2 <sup>(2)</sup>   | 2.2 | 3.3 |           | μH   |

- (1) When using an external resistor divider at DEFDCDC3, DEFDCDC2, DEFDCDC1
- (2) See applications section for more information.

|                  |   |     |     |                    |
|------------------|---|-----|-----|--------------------|
| $C_{I(DCDC2)}$   | Input Capacitor at VINDCDC2 <sup>(2)</sup>  | 10  |     | $\mu\text{F}$      |
| $C_{O(DCDC2)}$   | Output Capacitor at VDCDC2 <sup>(2)</sup>   | 10  | 22  | $\mu\text{F}$      |
| $I_{O(DCDC3)}$   | Output current at L3  |     | 900 | mA                 |
|                  | Inductor at L3 <sup>(2)</sup>   | 2.2 | 3.3 | $\mu\text{H}$      |
| $C_{I(DCDC3)}$   | Input Capacitor at VINDCDC3 <sup>(2)</sup>  | 10  |     | $\mu\text{F}$      |
| $C_{O(DCDC3)}$   | Output Capacitor at VDCDC3 <sup>(2)</sup>   | 10  | 22  | $\mu\text{F}$      |
| $C_{I(VCC)}$     | Input Capacitor at VCC <sup>(2)</sup>   | 1   |     | $\mu\text{F}$      |
| $C_{I(VINLDO)}$  | Input Capacitor at VINLDO <sup>(2)</sup>  | 1   |     | $\mu\text{F}$      |
| $C_{O(VLDO1-2)}$ | Output Capacitor at VLDO1, VLDO2 <sup>(2)</sup>                                     | 2.2 |     | $\mu\text{F}$      |
| $I_{O(VLDO1-2)}$ | Output current at VLDO1, VLDO2  |     | 200 | mA                 |
| $C_{O(VRTC)}$    | Output Capacitor at VRTC <sup>(3)</sup>   | 4.7 |     | $\mu\text{F}$      |
| $T_A$            | Operating ambient temperature   | -40 | 85  | $^{\circ}\text{C}$ |
| $T_J$            | Operating junction temperature  | -40 | 125 | $^{\circ}\text{C}$ |
|                  | Resistor from VINDCDC3, VINDCDC2, VINDCDC1 to VCC used for filtering <sup>(4)</sup> | 1   | 10  | $\Omega$           |

(3) See applications section for more information.

(4) Up to 3 mA can flow into  $V_{CC}$  when all 3 converters are running in PWM. This resistor causes the UVLO threshold to be shifted accordingly.

## ELECTRICAL CHARACTERISTICS

VINDCDC1 = VINDCDC2 = VINDCDC3 = VCC = VINLDO = 3.6 V, VBACKUP = 3 V,  $T_A = -40^{\circ}\text{C}$  to  $85^{\circ}\text{C}$ , typical values are at  $T_A = 25^{\circ}\text{C}$  (unless otherwise noted)

| PARAMETER   | TEST CONDITIONS                   | MIN  | TYP  | MAX      | UNIT          |
|---|-----------------------------------|--|------|----------|---------------|
| <b>CONTROL SIGNALS : SCLK, SDAT (input), DCDC1_EN, DCDC2_EN, DCDC3_EN, LDO_EN, DEFLDO1, DEFLDO2</b> |                                   |  |      |          |               |
| $V_{IH}$  | High level input voltage          | Rpullup at SCLK and SDAT = 4.7 k $\Omega$ , pulled to VRTC |      | VCC      | V             |
| $V_{IL}$  | Low level input voltage           | Rpullup at SCLK and SDAT = 4.7 k $\Omega$ , pulled to VRTC |      | 0.4      | V             |
| $I_H$   | Input bias current                |  | 0.01 | 0.1      | $\mu\text{A}$ |
| <b>CONTROL SIGNALS : HOT_RESET</b>  |                                   |  |      |          |               |
| $V_{IH}$  | High level input voltage          |  | 1.3  | VCC      | V             |
| $V_{IL}$  | Low level input voltage           |  | 0    | 0.4      | V             |
| $I_{IB}$  | Input bias current                |  | 0.01 | 0.1      | $\mu\text{A}$ |
| $t_{\text{glitch}}$   | Deglitch time at HOT_RESET        |  | 25   | 30       | 35            |
| <b>CONTROL SIGNALS : LOWBAT, PWRFAIL, RESPWRON, INT, SDAT (output)</b>                              |                                   |  |      |          |               |
| $V_{OH}$  | High level output voltage         |  |      | 6        | V             |
| $V_{OL}$  | Low level output voltage          | $I_{IL} = 5 \text{ mA}$                                    |      | 0.3      | V             |
|   | Duration of low pulse at RESPWRON | External capacitor 1 nF                                    |      | 100      | ms            |
|   | Resetpwron threshold              | VRTC falling   |      | -3% 2.4  | 3% V          |
|   | Resetpwron threshold              | VRTC rising  |      | -3% 2.52 | 3% V          |

**ELECTRICAL CHARACTERISTICS**

VINDCDC1 = VINDCDC2 = VINDCDC3 = VCC = VINLDO = 3.6 V, VBACKUP = 3 V, T<sub>A</sub> = –40°C to 85°C, typical values are at T<sub>A</sub> = 25°C (unless otherwise noted)

| PARAMETER   | TEST CONDITIONS  | MIN   | TYP  | MAX | UNIT |
|---|--|---|------|-----|------|
| <b>SUPPLY PINS: VCC, VINDCDC1, VINDCDC2, VINDCDC3</b> |  |   |      |     |      |
| I <sub>(q)</sub> Operating quiescent current, PFM     | All 3 DCDC converters enabled, zero load and no switching, LDOs enabled  | VCC = 3.6 V, VBACKUP = 3 V; V <sub>(VSYSIN)</sub> = 0 V | 85   | 100 | μA   |
|   | All 3 DCDC converters enabled, zero load and no switching, LDOs off      | VCC = 3.6 V, VBACKUP = 3 V; V <sub>(VSYSIN)</sub> = 0 V | 78   | 90  |      |
|   | DCDC1 and DCDC2 converters enabled, zero load and no switching, LDOs off | VCC = 3.6 V, VBACKUP = 3 V; V <sub>(VSYSIN)</sub> = 0 V | 57   | 70  |      |
|   | DCDC1 converter enabled, zero load and no switching, LDOs off            | VCC = 3.6 V, VBACKUP = 3 V; V <sub>(VSYSIN)</sub> = 0 V | 43   | 55  |      |
| I <sub>I</sub> Current into VCC; PWM                  | All 3 DCDC converters enabled and running in PWM, LDOs off               | VCC = 3.6 V, VBACKUP = 3 V; V <sub>(VSYSIN)</sub> = 0 V | 2    | 3   | mA   |
|   | DCDC1 and DCDC2 converters enabled and running in PWM, LDOs off          | VCC = 3.6 V, VBACKUP = 3 V; V <sub>(VSYSIN)</sub> = 0 V | 1.5  | 2.5 |      |
|   | DCDC1 converter enabled and running in PWM, LDOs off                     | VCC = 3.6 V, VBACKUP = 3 V; V <sub>(VSYSIN)</sub> = 0 V | 0.85 | 2   |      |
| I <sub>(q)</sub> Quiescent current                    | All converters disabled, LDOs off  | VCC = 3.6 V, VBACKUP = 3 V; V <sub>(VSYSIN)</sub> = 0 V | 23   | 33  | μA   |
|   |  | VCC = 2.6 V, VBACKUP = 3 V; V <sub>(VSYSIN)</sub> = 0 V | 3.5  | 5   | μA   |
|   |  | VCC = 3.6 V, VBACKUP = 0 V; V <sub>(VSYSIN)</sub> = 0 V |      | 43  | μA   |

## ELECTRICAL CHARACTERISTICS

VINDCDC1 = VINDCDC2 = VINDCDC3 = VCC = VINLDO = 3.6 V, VBACKUP = 3 V, T<sub>A</sub> = –40°C to 85°C, typical values are at T<sub>A</sub> = 25°C (unless otherwise noted)

| PARAMETER                          |   | TEST CONDITIONS   | MIN  | TYP  | MAX  | UNIT |
|------------------------------------|---|---|------|------|------|------|
| SUPPLY PINS: VBACKUP, VSYSIN, VRTC |   |   |      |      |      |      |
| I <sub>(q)</sub>                   | Operating quiescent current                     | VBACKUP = 3 V, VSYSIN = 0 V;<br>VCC = 2.6 V, current into VBACKUP | 20   | 33   |      | μA   |
| I <sub>(SD)</sub>                  | Operating quiescent current                     | VBACKUP < V_VBACKUP, current into VBACKUP                         | 2    | 3    |      | μA   |
|                                    | VRTC LDO output voltage                         | VSYSIN = VBACKUP = 0 V, I <sub>O</sub> = 0 mA                     | 3    |      |      | V    |
| I <sub>O</sub>                     | Output current for VRTC                         | VSYSIN < 2.57 V and VBACKUP < 2.57 V                              |      |      | 30   | mA   |
|                                    | VRTC short-circuit current limit                | VRTC = GND; VSYSIN = VBACKUP = 0 V                                |      |      | 100  | mA   |
|                                    | Maximum output current at VRTC for RESPWRON = 1 | VRTC > 2.6 V, V <sub>CC</sub> = 3 V;<br>VSYSIN = VBACKUP = 0 V    | 30   |      |      | mA   |
| V <sub>O</sub>                     | Output voltage accuracy for VRTC                | VSYSIN = VBACKUP = 0 V; I <sub>O</sub> = 0 mA                     | -1%  |      | 1%   |      |
|                                    | Line regulation for VRTC                        | VCC = VRTC + 0.5 V to 6.5 V, I <sub>O</sub> = 5 mA                | -1%  |      | 1%   |      |
|                                    | Load regulation VRTC                            | I <sub>O</sub> = 1 mA to 30 mA;<br>VSYSIN = VBACKUP = 0 V         | -3%  |      | 1%   |      |
|                                    | Regulation time for VRTC                        | Load change from 10% to 90%                                       | 10   |      |      | μs   |
| I <sub>lkg</sub>                   | Input leakage current at VSYSIN                 | VSYSIN < V_VSYSIN   |      |      | 2    | μA   |
|                                    | r <sub>DS(on)</sub> of VSYSIN switch            |   |      |      | 12.5 | Ω    |
|                                    | r <sub>DS(on)</sub> of VBACKUP switch           |   |      |      | 12.5 | Ω    |
|                                    | Input voltage range at VBACKUP <sup>(1)</sup>   |   | 2.73 |      | 3.75 | V    |
|                                    | Input voltage range at VSYSIN <sup>(1)</sup>    |   | 2.73 |      | 3.75 | V    |
|                                    | VSYSIN threshold                                | VSYSIN falling  | -3%  | 2.55 | 3%   | V    |
|                                    | VSYSIN threshold                                | VSYSIN rising   | -3%  | 2.65 | 3%   | V    |
|                                    | VBACKUP threshold                               | VBACKUP falling   | -3%  | 2.55 | 3%   | V    |
|                                    | VBACKUP threshold                               | VBACKUP falling   | -3%  | 2.65 | 3%   | V    |
| SUPPLY PIN: VINLDO                 |   |   |      |      |      |      |
| I <sub>(q)</sub>                   | Operating quiescent current                     | Current per LDO into VINLDO                                       | 16   | 30   |      | μA   |
| I <sub>(SD)</sub>                  | Shutdown current                                | Total current for both LDOs into VINLDO,<br>VLDO = 0 V            | 0.1  | 1    |      | μA   |

(1) Based on the requirements for the Intel PXA270 processor.

**ELECTRICAL CHARACTERISTICS**

VINDCDC1 = VINDCDC2 = VINDCDC3 = VCC = VINLDO = 3.6 V, VBACKUP = 3 V, T<sub>A</sub> = –40°C to 85°C, typical values are at T<sub>A</sub> = 25°C (unless otherwise noted)

| PARAMETER   |  | TEST CONDITIONS   | MIN  | TYP  | MAX  | UNIT |
|---|--|---|------|------|------|------|
| <b>VDCDC1 STEP-DOWN CONVERTER</b>   |  |   |      |      |      |      |
| V <sub>I</sub>  | Input voltage range, VINDCDC1            |   | 2.5  |      | 6    | V    |
| I <sub>O</sub>  | Maximum output current                   |   | 1200 |      |      | mA   |
| I <sub>(SD)</sub>   | Shutdown supply current in VINDCDC1      | DCDC1_EN = GND  |      | 0.1  | 1    | μA   |
| r <sub>DS(on)</sub>   | P-channel MOSFET on-resistance           | VINDCDC1 = V <sub>(GS)</sub> = 3.6 V  |      | 125  | 261  | mΩ   |
| I <sub>lkg</sub>  | P-channel leakage current                | VINDCDC1 = 6 V  |      |      | 2    | μA   |
| r <sub>DS(on)</sub>   | N-channel MOSFET on-resistance           | VINDCDC1 = V <sub>(GS)</sub> = 3.6 V  |      | 130  | 260  | mΩ   |
| I <sub>lkg</sub>  | N-channel leakage current                | V <sub>(DS)</sub> = 6 V   |      | 7    | 10   | μA   |
|   | Forward current limit (P- and N-channel) | 2.5 V < V <sub>I(MAIN)</sub> < 6 V  | 1.55 | 1.75 | 1.95 | A    |
| f <sub>S</sub>  | Oscillator frequency                     |   | 1.3  | 1.5  | 1.7  | MHz  |
| Fixed output voltage<br>FPWMDCDC1=0   | 3 V                                      | VINDCDC1 = 3.3 V to 6 V;<br>0 mA ≤ I <sub>O</sub> ≤ 1.2 A                     | –2%  |      | 2%   |      |
|   | 3.3 V                                    | VINDCDC1 = 3.6 V to 6 V;<br>0 mA ≤ I <sub>O</sub> ≤ 1.2 A                     | –2%  |      | 2%   |      |
| Fixed output voltage<br>FPWMDCDC1=1   | 3 V                                      | VINDCDC1 = 3.3 V to 6 V;<br>0 mA ≤ I <sub>O</sub> ≤ 1.2 A                     | –1%  |      | 1%   |      |
|   | 3.3 V                                    | VINDCDC1 = 3.6 V to 6 V;<br>0 mA ≤ I <sub>O</sub> ≤ 1.2 A                     | –1%  |      | 1%   |      |
| Adjustable output voltage with resistor<br>divider at DEFDCDC1; FPWMDCDC1=0 |  | VINDCDC1 = VDCDC1 +0.3 V (min 2.5 V)<br>to 6 V; 0 mA ≤ I <sub>O</sub> ≤ 1.2 A | –2%  |      | 2%   |      |
| Adjustable output voltage with resistor<br>divider at DEFDCDC1; FPWMDCDC1=1 |  | VINDCDC1 = VDCDC1 +0.3 V (min 2.5 V)<br>to 6 V; 0 mA ≤ I <sub>O</sub> ≤ 1.2 A | –1%  |      | 1%   |      |
| Line Regulation   |  | VINDCDC1 = VDCDC1 + 0.3 V (min. 2.5 V)<br>to 6 V; I <sub>O</sub> = 10 mA      |      | 0    |      | %/V  |
| Load Regulation   |  | I <sub>O</sub> = 10 mA to 1200 mA   |      | 0.25 |      | %/A  |
| Soft start ramp time  |  | VDCDC1 ramping from 5% to 95% of target<br>value                              |      | 750  |      | μs   |
| Internal resistance from L1 to GND  |  |   |      | 1    |      | MΩ   |
| VDCDC1 discharge resistance   |  | DCDC1 discharge = 1   |      | 300  |      | Ω    |

## ELECTRICAL CHARACTERISTICS

VINDCDC1 = VINDCDC2 = VINDCDC3 = VCC = VINLDO = 3.6 V, VBACKUP = 3 V, T<sub>A</sub> = –40°C to 85°C, typical values are at T<sub>A</sub> = 25°C (unless otherwise noted)

| PARAMETER   |  | TEST CONDITIONS   | MIN  | TYP  | MAX | UNIT |
|---|--|---|------|------|-----|------|
| <b>VDCDC2 STEP-DOWN CONVERTER</b>   |  |   |      |      |     |      |
| V <sub>I</sub>  | Input voltage range, VINDCDC2            |   | 2.5  |      | 6   | V    |
| I <sub>O</sub>  | Maximum output current                   |   | 1000 |      |     | mA   |
| I <sub>(SD)</sub>   | Shutdown supply current in VINDCDC2      | DCDC2_EN = GND  |      | 0.1  | 1   | μA   |
| r <sub>DS(on)</sub>   | P-channel MOSFET on-resistance           | VINDCDC2 = V <sub>(GS)</sub> = 3.6 V  |      | 140  | 300 | mΩ   |
| I <sub>lkg</sub>  | P-channel leakage current                | VINDCDC2 = 6 V  |      |      | 2   | μA   |
| r <sub>DS(on)</sub>   | N-channel MOSFET on-resistance           | VINDCDC2 = V <sub>(GS)</sub> = 3.6 V  |      | 150  | 297 | mΩ   |
| I <sub>lkg</sub>  | N-channel leakage current                | V <sub>(DS)</sub> = 6 V   |      | 7    | 10  | μA   |
| I <sub>LIMF</sub>   | Forward current limit (P- and N-channel) | 2.5 V < VINDCDC2 < 6 V  | 1.4  | 1.55 | 1.7 | A    |
| f <sub>S</sub>  | Oscillator frequency                     |   | 1.3  | 1.5  | 1.7 | MHz  |
| Fixed output voltage<br>FPWMDCDC2=0   | 1.8 V                                    | VINDCDC2 = 2.5 V to 6 V;<br>0 mA ≤ I <sub>O</sub> ≤ 1 A                     | –2%  |      | 2%  |      |
|   | 2.5 V                                    | VINDCDC2 = 2.8 V to 6 V;<br>0 mA ≤ I <sub>O</sub> ≤ 1 A                     | –2%  |      | 2%  |      |
| Fixed output voltage<br>FPWMDCDC2=1   | 1.8 V                                    | VINDCDC2 = 2.5 V to 6 V;<br>0 mA ≤ I <sub>O</sub> ≤ 1 A                     | –2%  |      | 2%  |      |
|   | 2.5 V                                    | VINDCDC2 = 2.8 V to 6 V;<br>0 mA ≤ I <sub>O</sub> ≤ 1 A                     | –1%  |      | 1%  |      |
| Adjustable output voltage with resistor<br>divider at DEFDCDC2 FPWMDCDC2=0  |  | VINDCDC2 = VDCDC2 +0.3 V (min 2.5 V)<br>to 6 V; 0 mA ≤ I <sub>O</sub> ≤ 1 A | –2%  |      | 2%  |      |
| Adjustable output voltage with resistor<br>divider at DEFDCDC2; FPWMDCDC2=1 |  | VINDCDC2 = VDCDC2 +0.3 V (min 2.5 V)<br>to 6 V; 0 mA ≤ I <sub>O</sub> ≤ 1 A | –1%  |      | 1%  |      |
| Line Regulation   |  | VINDCDC2 = VDCDC2 + 0.3 V (min. 2.5 V)<br>to 6 V; I <sub>O</sub> = 10 mA    |      | 0    |     | %/V  |
| Load Regulation   |  | I <sub>O</sub> = 10 mA to 1 mA  |      | 0.25 |     | %/A  |
| Soft start ramp time  |  | VDCDC2 ramping from 5% to 95% of target<br>value                            |      | 750  |     | μs   |
| Internal resistance from L2 to GND  |  |   |      | 1    |     | MΩ   |
| VDCDC2 discharge resistance   |  | DCDC2 discharge =1  |      | 300  |     | Ω    |

**ELECTRICAL CHARACTERISTICS**

VINDCDC1 = VINDCDC2 = VINDCDC3 = VCC = VINLDO = 3.6 V, VBACKUP = 3 V,  $T_A = -40^{\circ}\text{C}$  to  $85^{\circ}\text{C}$ , typical values are at  $T_A = 25^{\circ}\text{C}$  (unless otherwise noted)

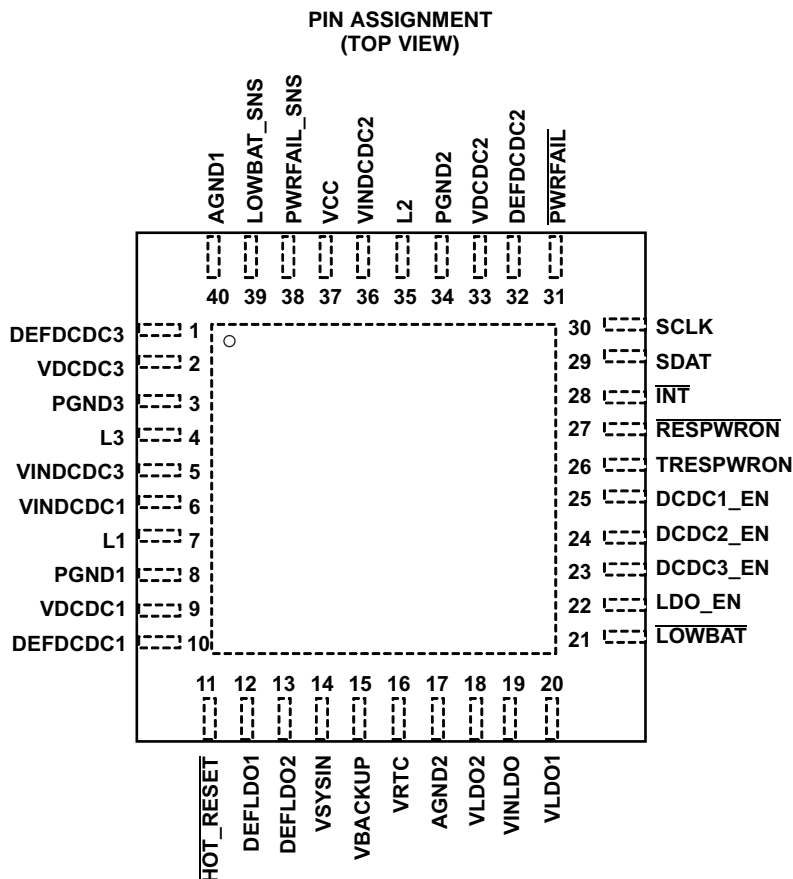
| PARAMETER                         |   |            | TEST CONDITIONS  | MIN  | TYP  | MAX  | UNIT             |
|-----------------------------------|---|------------|--|------|------|------|------------------|
| <b>VDCDC3 STEP-DOWN CONVERTER</b> |   |            |  |      |      |      |                  |
| $V_I$                             | Input voltage range, VINDCDC3   |            |  | 2.5  |      | 6    | V                |
| $I_O$                             | Maximum output current  |            |  | 900  |      |      | mA               |
| $I_{SD}$                          | Shutdown supply current in VINDCDC3   |            | DCDC3_EN = GND   |      | 0.1  | 1    | $\mu\text{A}$    |
| $r_{DS(on)}$                      | P-channel MOSFET on-resistance  |            | VINDCDC3 = $V_{(GS)} = 3.6\text{ V}$   |      | 310  | 698  | $\text{m}\Omega$ |
| $I_{lkg}$                         | P-channel leakage current   |            | VINDCDC3 = 6 V   |      | 0.1  | 2    | $\mu\text{A}$    |
| $r_{DS(on)}$                      | N-channel MOSFET on-resistance  |            | VINDCDC3 = $V_{(GS)} = 3.6\text{ V}$   |      | 220  | 503  | $\text{m}\Omega$ |
| $I_{lkg}$                         | N-channel leakage current   |            | $V_{(DS)} = 6\text{ V}$  |      | 7    | 10   | $\mu\text{A}$    |
|                                   | Forward current limit (P- and N-channel)                                    |            | $2.5\text{ V} < \text{VINDCDC3} < 6\text{ V}$  | 1.15 | 1.34 | 1.52 | A                |
| $f_S$                             | Oscillator frequency  |            |  | 1.3  | 1.5  | 1.7  | MHz              |
|                                   | Fixed output voltage<br>FPWMDCDC3=0   | All VDCDC3 | VINDCDC3 = 2.5 V to 6 V;<br>$0\text{ mA} \leq I_O \leq 800\text{ mA}$                      | -2%  |      | 2%   |                  |
|                                   | Fixed output voltage<br>FPWMDCDC3=1   |            | VINDCDC3 = 2.5 V to 6 V;<br>$0\text{ mA} \leq I_O \leq 800\text{ mA}$                      | -1%  |      | 1%   |                  |
|                                   | Adjustable output voltage with resistor<br>divider at DEFDCDC3 FPWMDCDC3=0  |            | VINDCDC3 = VDCDC3 + 0.5 V (min 2.5 V)<br>to 6 V; $0\text{ mA} \leq I_O \leq 800\text{ mA}$ | -2%  |      | 2%   |                  |
|                                   | Adjustable output voltage with resistor<br>divider at DEFDCDC3; FPWMDCDC3=1 |            | VINDCDC3 = VDCDC3 + 0.5 V (min 2.5 V)<br>to 6 V; $0\text{ mA} \leq I_O \leq 800\text{ mA}$ | -1%  |      | 1%   |                  |
|                                   | Line Regulation   |            | VINDCDC3 = VDCDC3 + 0.3 V (min. 2.5 V)<br>to 6 V; $I_O = 10\text{ mA}$                     |      | 0    |      | %/V              |
|                                   | Load Regulation   |            | $I_O = 10\text{ mA}$ to 400 mA   |      | 0.25 |      | %/A              |
|                                   | Soft start ramp time  |            | VDCDC3 ramping from 5% to 95% of target<br>value   |      | 750  |      | $\mu\text{s}$    |
|                                   | Internal resistance from L3 to GND  |            |  |      | 1    |      | $\text{M}\Omega$ |
|                                   | VDCDC3 discharge resistance   |            | DCDC3 discharge = 1  |      | 300  |      | $\Omega$         |



## ELECTRICAL CHARACTERISTICS

VINDCDC1 = VINDCDC2 = VINDCDC3 = VCC = VINLDO = 3.6 V, VBACKUP = 3 V, T<sub>A</sub> = –40°C to 85°C, typical values are at T<sub>A</sub> = 25°C (unless otherwise noted)

| PARAMETER  |  | TEST CONDITIONS  | MIN  | TYP   | MAX  | UNIT |
|--|--|--|------|-------|------|------|
| <b>VLDO1 and VLDO2 LOW DROPOUT REGULATORS</b>        |  |  |      |       |      |      |
| V <sub>I</sub>                                       | Input voltage range for LDO1, 2                |  | 1.5  |       | 6.5  | V    |
| V <sub>O</sub>                                       | LDO1 output voltage range                      |  | 1    |       | 3.3  | V    |
| V <sub>O</sub>                                       | LDO2 output voltage range                      |  | 1    |       | 3.3  | V    |
| I <sub>O</sub>                                       | Maximum output current for LDO1, LDO2          | V <sub>I</sub> = 1.8 V, V <sub>O</sub> = 1.3 V<br>V <sub>I</sub> = 1.5 V, V <sub>O</sub> = 1.3 V | 200  | 120   |      | mA   |
| I <sub>(SC)</sub>                                    | LDO1 and LDO2 short circuit current limit      | V <sub>(LDO1)</sub> = GND, V <sub>(LDO2)</sub> = GND   |      |       | 400  | mA   |
|  | Minimum voltage drop at LDO1, LDO2             | I <sub>O</sub> = 50 mA, VINLDO = 1.8 V   |      |       | 120  | mV   |
|  |  | I <sub>O</sub> = 50 mA, VINLDO = 1.5 V   |      | 65    | 150  |      |
|  |  | I <sub>O</sub> = 200 mA, VINLDO = 1.8 V  |      |       | 300  |      |
|  | Output voltage accuracy for LDO1, LDO2         | I <sub>O</sub> = 10 mA   | –2%  |       | 1%   |      |
|  | Line regulation for LDO1, LDO2                 | VINLDO1,2 = VLDO1,2 + 0.5 V (min. 2.5 V) to 6.5 V, I <sub>O</sub> = 10 mA                        | –1%  |       | 1%   |      |
|  | Load regulation for LDO1, LDO2                 | I <sub>O</sub> = 0 mA to 50 mA   | –1%  |       | 1%   |      |
|  | Regulation time for LDO1, LDO2                 | Load change from 10% to 90%  |      | 10    |      | μs   |
| <b>ANALOGIC SIGNALS DEFDCDC1, DEFDCDC2, DEFDCDC3</b> |  |  |      |       |      |      |
| V <sub>IH</sub>                                      | High level input voltage                       |  | 1.3  |       | VCC  | V    |
| V <sub>IL</sub>                                      | Low level input voltage                        |  | 0    |       | 0.1  | V    |
|  | Input bias current                             |  |      | 0.001 | 0.05 | μA   |
| <b>THERMAL SHUTDOWN</b>                              |  |  |      |       |      |      |
| T <sub>(SD)</sub>                                    | Thermal shutdown                               | Increasing junction temperature  |      | 160   |      | °C   |
|  | Thermal shutdown hysteresis                    | Decreasing junction temperature  |      | 20    |      | °C   |
| <b>INTERNAL UNDERVOLTAGE LOCK OUT</b>                |  |  |      |       |      |      |
| UVLO   | Internal UVLO                                  | VCC falling  | –2%  | 2.35  | 2%   | V    |
| V <sub>(UVLO_HYST)</sub>                             | Internal UVLO comparator hysteresis            |  |      | 120   |      | mV   |
| <b>VOLTAGE DETECTOR COMPARATORS</b>                  |  |  |      |       |      |      |
|  | Comparator threshold (PWRFAIL_SNS, LOWBAT_SNS) | Falling threshold  | –1%  | 1     | 1%   | V    |
|  | Hysteresis                                     |  | 40   | 50    | 60   | mV   |
|  | Propagation delay                              | 25 mV overdrive  |      |       | 10   | μs   |
| <b>POWER GOOD</b>                                    |  |  |      |       |      |      |
| V <sub>(PGOODF)</sub>                                |  | VDCDC1, VDCDC2, VDCDC3, VLDO1, VLDO2, decreasing   | –12% | –10%  | –8%  |      |
| V <sub>(PGOODR)</sub>                                |  | VDCDC1, VDCDC2, VDCDC3, VLDO1, VLDO2, increasing   | –7%  | –5%   | –3%  |      |

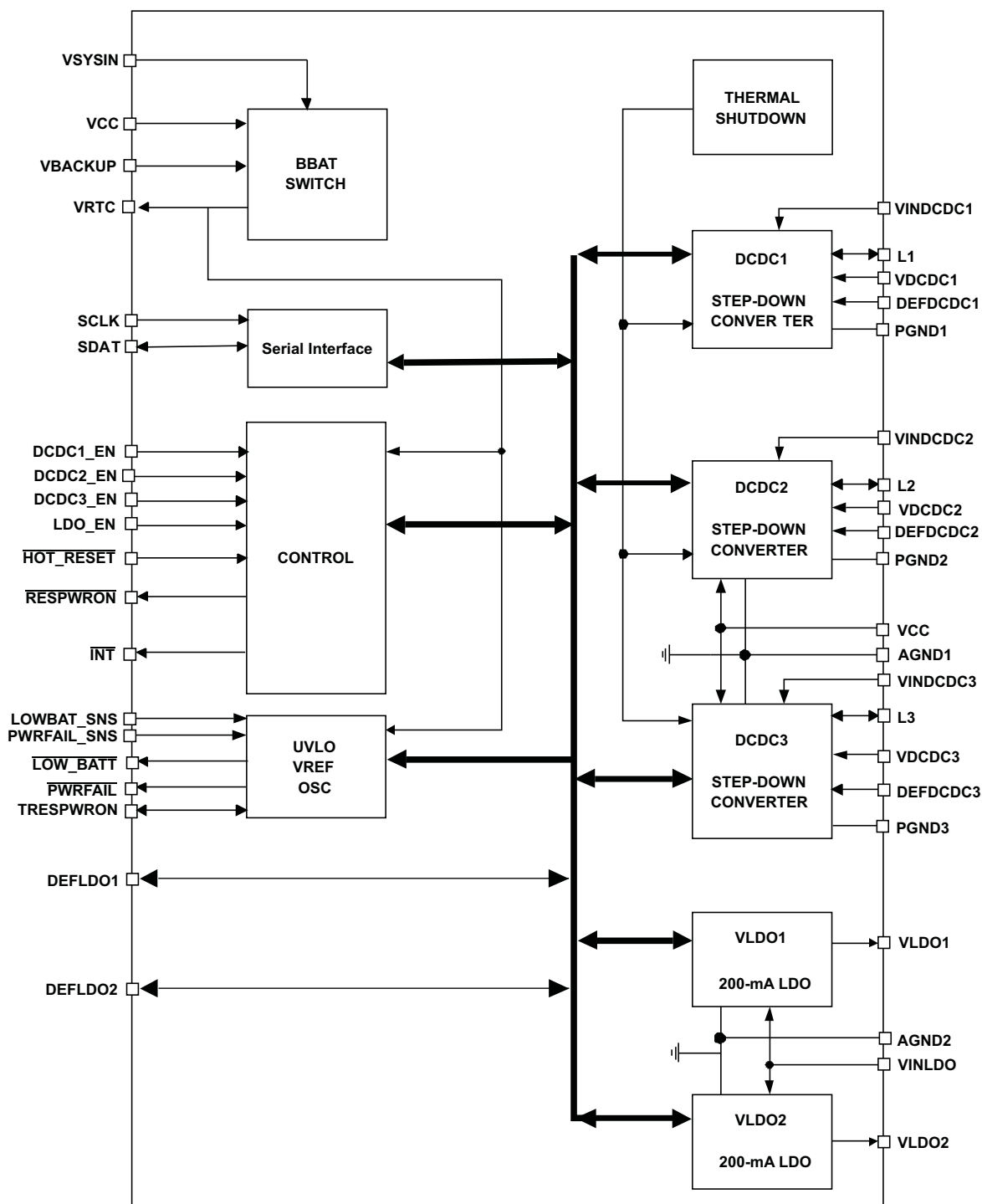
**TERMINAL FUNCTIONS**

| TERMINAL                    |     | I/O | DESCRIPTION   |
|-----------------------------|-----|-----|---|
| NAME                        | NO. |     |   |
| SWITCHING REGULATOR SECTION |     |     |   |
| AGND1                       | 40  |     | Analog ground connection. All analog ground pins are connected internally on the chip.  |
| AGND2                       | 17  |     | Analog ground connection. All analog ground pins are connected internally on the chip.  |
| PowerPAD™                   | –   |     | Connect the power pad to analog ground.   |
| VINDCDC1                    | 6   | I   | Input voltage for VDCDC1 step-down converter. This must be connected to the same voltage supply as VINDCDC2, VINDCDC3, and VCC.   |
| L1                          | 7   |     | Switch pin of VDCDC1 converter. The VDCDC1 inductor is connected here.  |
| VDCDC1                      | 9   | I   | VDCDC1 feedback voltage sense input, connect directly to VDCDC1   |
| PGND1                       | 8   |     | Power ground for VDCDC1 converter   |
| VINDCDC2                    | 36  | I   | Input voltage for VDCDC2 step-down converter. This must be connected to the same voltage supply as VINDCDC1, VINDCDC3, and VCC.   |
| L2                          | 35  |     | Switch pin of VDCDC2 converter. The VDCDC2 inductor is connected here.  |
| VDCDC2                      | 33  | I   | VDCDC2 feedback voltage sense input, connect directly to VDCDC2   |
| PGND2                       | 34  |     | Power ground for VDCDC2 converter   |
| VINDCDC3                    | 5   | I   | Input voltage for VDCDC3 step-down converter. This must be connected to the same voltage supply as VINDCDC1, VINDCDC2, and VCC.   |
| L3                          | 4   |     | Switch pin of VDCDC3 converter. The VDCDC3 inductor is connected here.  |
| VDCDC3                      | 2   | I   | VDCDC3 feedback voltage sense input, connect directly to VDCDC3   |
| PGND3                       | 3   |     | Power ground for VDCDC3 converter   |
| VCC                         | 37  | I   | Power supply for digital and analog circuitry of VDCDC1, VDCDC2, and VDCDC3 dc-dc converters. This must be connected to the same voltage supply as VINDCDC3, VINDCDC1, and VINDCDC2. Also supplies serial interface block |

**TERMINAL FUNCTIONS (continued)**

| TERMINAL                                  |     | I/O | DESCRIPTION   |
|---|-----|-----|---|
| NAME                                      | NO. |     |   |
| DEFDCDC1                                  | 10  | I   | Input signal indicating default VDCDC1 voltage, 0 = 3 V, 1 = 3.3 V This pin can also be connected to a resistor divider between VDCDC1 and GND. If the output voltage of the DCDC1 converter is set in a range from 0.6 V to VINDCDC1 V.    |
| DEFDCDC2                                  | 32  | I   | Input signal indicating default VDCDC2 voltage, 0 = 1.8 V, 1 = 2.5 V This pin can also be connected to a resistor divider between VDCDC2 and GND. If the output voltage of the DCDC2 converter is set in a range from 0.6 V to VINDCDC2 V.  |
| DEFDCDC3                                  | 1   | I   | Input signal indicating default VDCDC3 voltage, 0 = 1.3 V, 1 = 1.55 V This pin can also be connected to a resistor divider between VDCDC3 and GND. If the output voltage of the DCDC3 converter is set in a range from 0.6 V to VINDCDC3 V. |
| DCDC1_EN                                  | 25  | I   | VDCDC1 enable pin. A logic high enables the regulator, a logic low disables the regulator.  |
| DCDC2_EN                                  | 24  | I   | VDCDC2 enable pin. A logic high enables the regulator, a logic low disables the regulator.  |
| DCDC3_EN                                  | 23  | I   | VDCDC3 enable pin. A logic high enables the regulator, a logic low disables the regulator.  |
| <b>LDO REGULATOR SECTION</b>              |     |     |   |
| VINLDO                                    | 19  | I   | I Input voltage for LDO1 and LDO2   |
| VLDO1                                     | 20  | O   | Output voltage of LDO1  |
| VLDO2                                     | 18  | O   | Output voltage of LDO2  |
| LDO_EN                                    | 22  | I   | Enable input for LDO1 and LDO2. Logic high enables the LDOs, logic low disables the LDOs  |
| VBACKUP                                   | 15  | I   | Connect the backup battery to this input pin.   |
| VRTC                                      | 16  | O   | Output voltage of the LDO/switch for the real time clock  |
| VSYSIN                                    | 14  | I   | Input of system voltage for VRTC switch   |
| DEFLD01                                   | 12  | I   | Digital input, used to set default output voltage of LDO1 and LDO2  |
| DEFLD02                                   | 13  | I   | Digital input, used to set default output voltage of LDO1 and LDO2  |
| <b>CONTROL AND I<sup>2</sup>C SECTION</b> |     |     |   |
| HOT_RESET                                 | 11  | I   | Push button input used to reboot or wake-up processor via RESPWRON output pin   |
| TRESPWRON                                 | 26  | I   | Connect the timing capacitor to this pin to set the reset delay time: 1 nF → 100 ms   |
| RESPWRON                                  | 27  | O   | Open drain System reset output  |
| PWRFAIL                                   | 31  | O   | Open drain output. Active low when PWRFAIL comparator indicates low VBAT condition.   |
| LOW_BAT                                   | 21  | O   | Open drain output of LOW_BAT comparator   |
| INT                                       | 28  | O   | Open drain output   |
| SCLK                                      | 30  | I   | Serial interface clock line   |
| SDAT                                      | 29  | I/O | Serial interface data/address   |
| PWRFAIL_SNS                               | 38  | I   | Input for the comparator driving the PWRFAIL output.  |
| LOWBAT_SNS                                | 39  | I   | Input for the comparator driving the LOW_BAT output.  |

## FUNCTIONAL BLOCK DIAGRAM



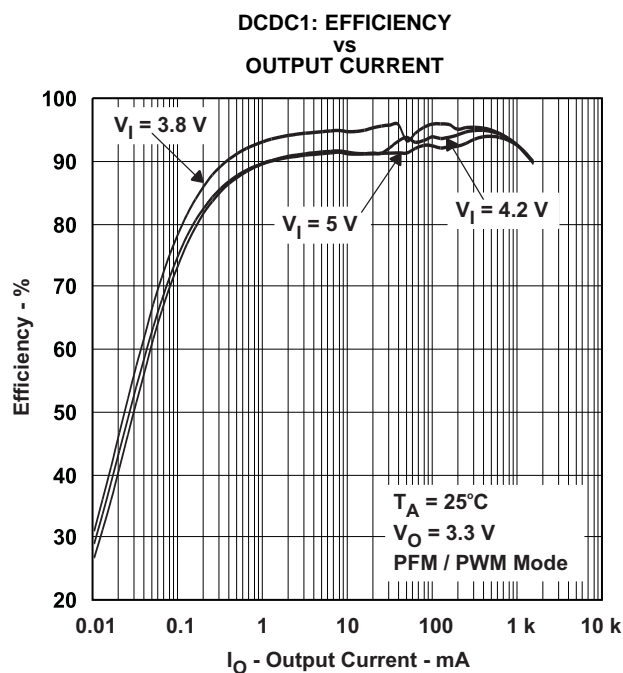
## TYPICAL CHARACTERISTICS

Graphs were taken using the EVM with the following inductor/output capacitor combinations:

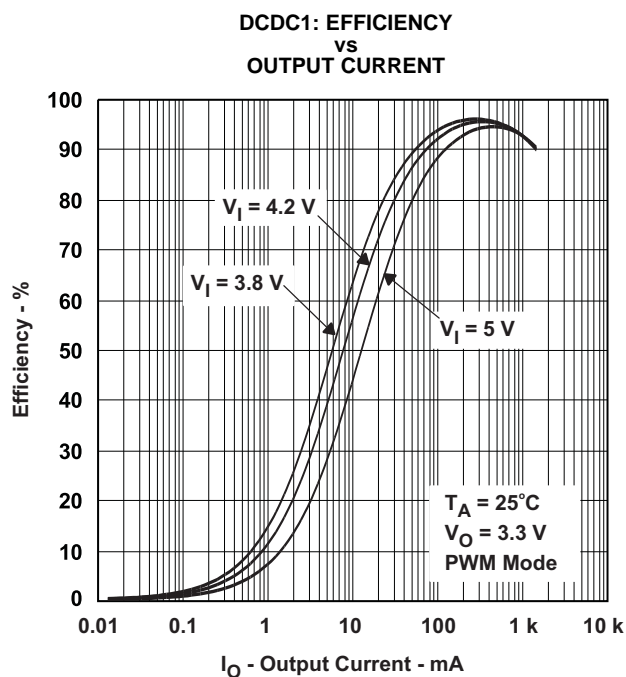
| CONVERTER | INDUCTOR          | OUTPUT CAPACITOR | OUTPUT CAPACITOR VALUE    |
|-----------|-------------------|------------------|---------------------------|
| VDCDC1    | VLCF4020-2R2      | C2012X5R0J106M   | $2 \times 10 \mu\text{F}$ |
| VDCDC2    | VLCF4020-2R2      | C2012X5R0J106M   | $2 \times 10 \mu\text{F}$ |
| VDCDC3    | VLF4012AT-2R2M1R5 | C2012X5R0J106M   | $2 \times 10 \mu\text{F}$ |

**Table 1. Table of Graphs**

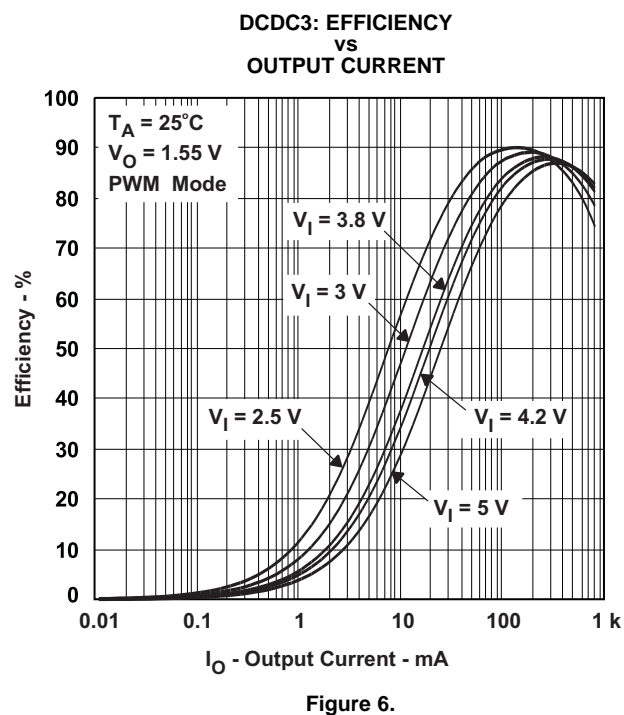
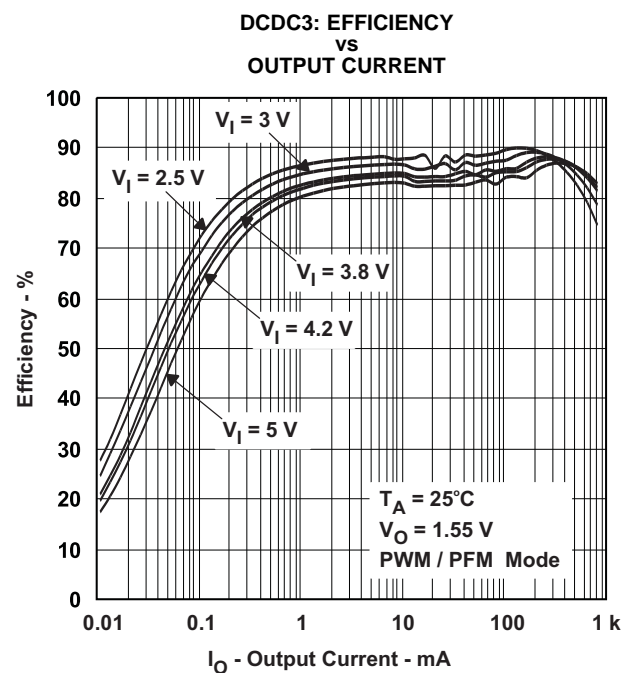
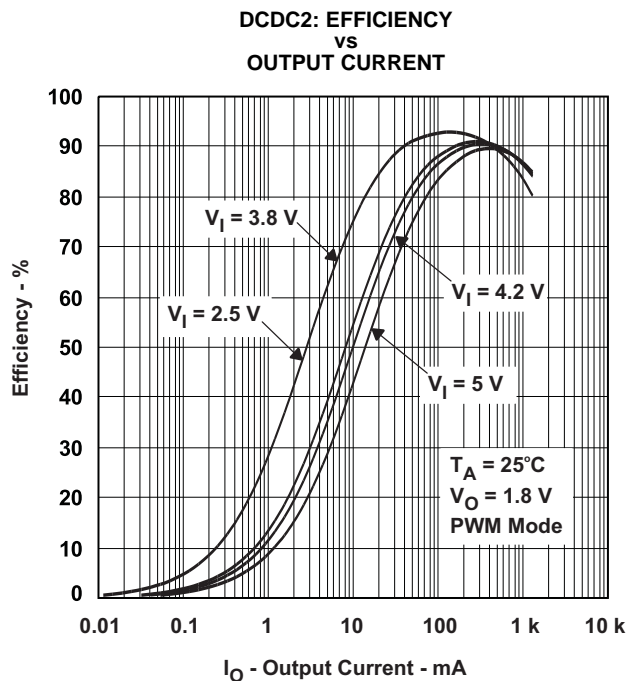
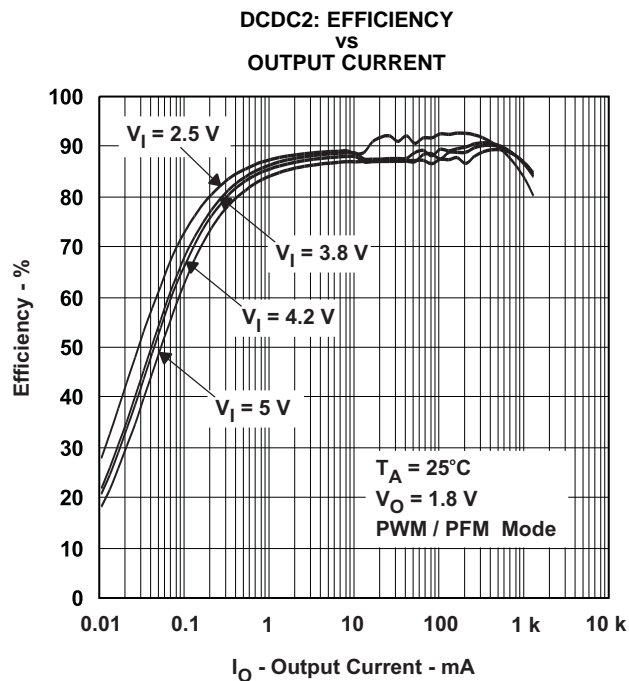
|        |                                   |                   | FIGURE              |
|--------|-----------------------------------|-------------------|---------------------|
| $\eta$ | Efficiency                        | vs Output current | 1, 2, 3, 4, 5, 6, 7 |
|        | Line transient response           |                   | 8, 9, 10            |
|        | Load transient response           |                   | 11, 12, 13          |
|        | VDCDC2 PFM operation              |                   | 14                  |
|        | VDCDC2 low ripple PFM operation   |                   | 15                  |
|        | VDCDC2 PWM operation              |                   | 16                  |
|        | Startup VDCDC1, VDCDC2 and VDCDC3 |                   | 17                  |
|        | Startup LDO1 and LDO2             |                   | 18                  |
|        | Line transient response           |                   | 19, 20, 21          |
|        | Load transient response           |                   | 22, 23, 24          |



**Figure 1.**



**Figure 2.**



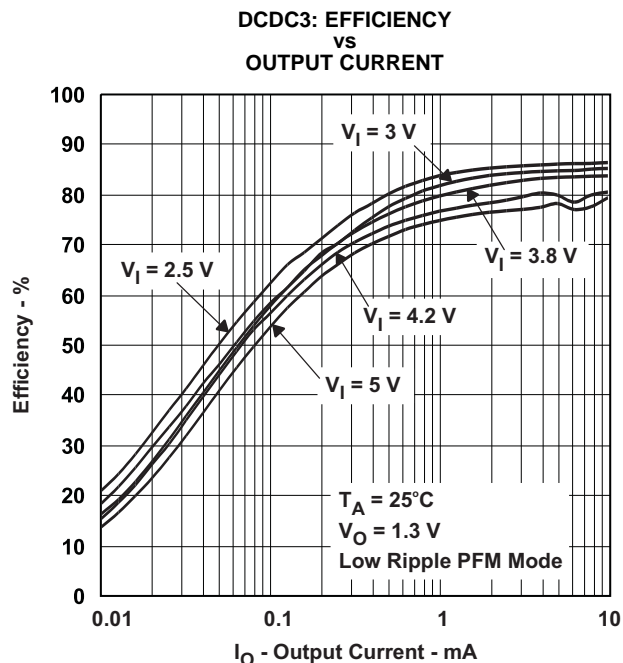


Figure 7.

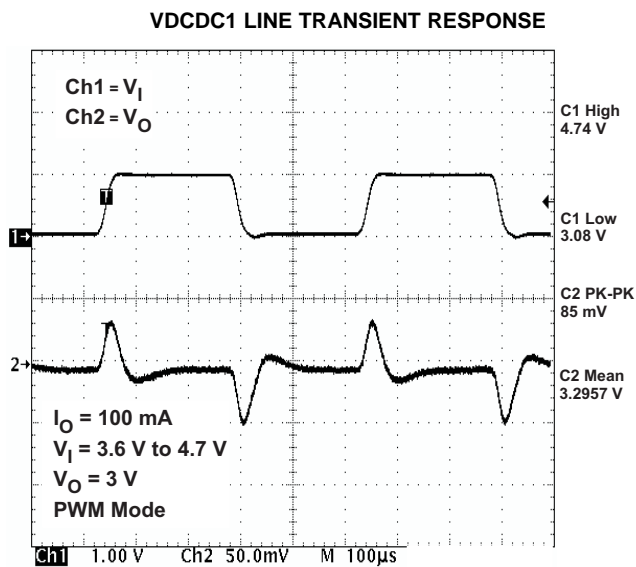


Figure 8.

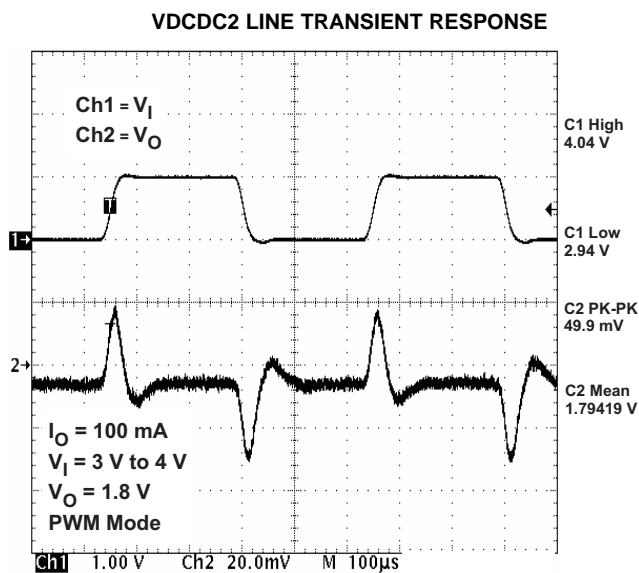


Figure 9.

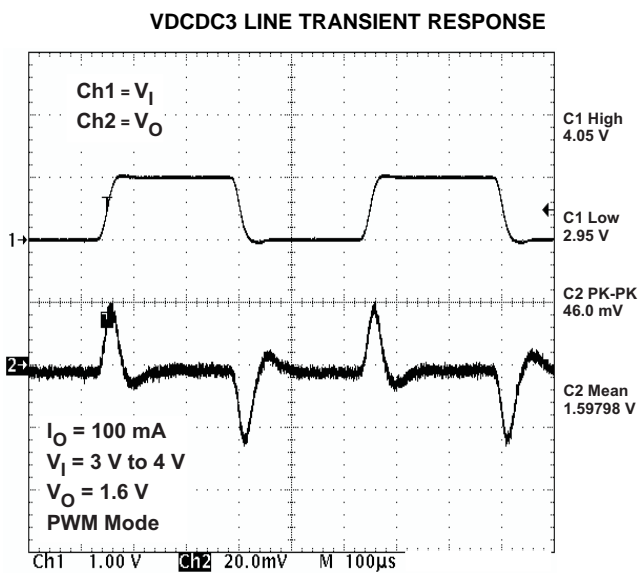


Figure 10.

VDCDC1 LOAD TRANSIENT RESPONSE

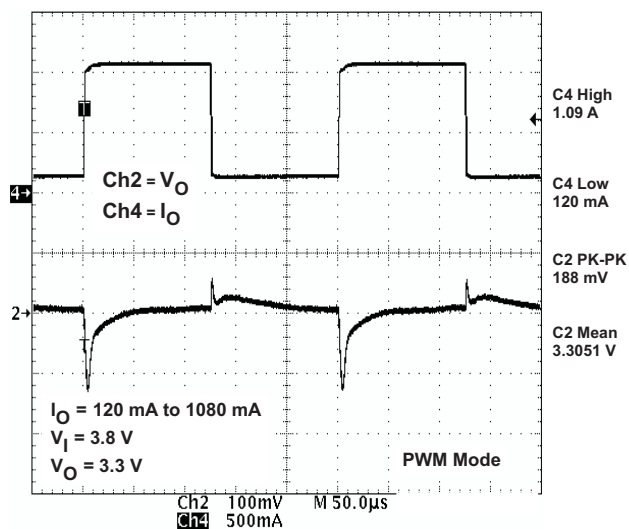


Figure 11.

VDCDC2 LOAD TRANSIENT RESPONSE

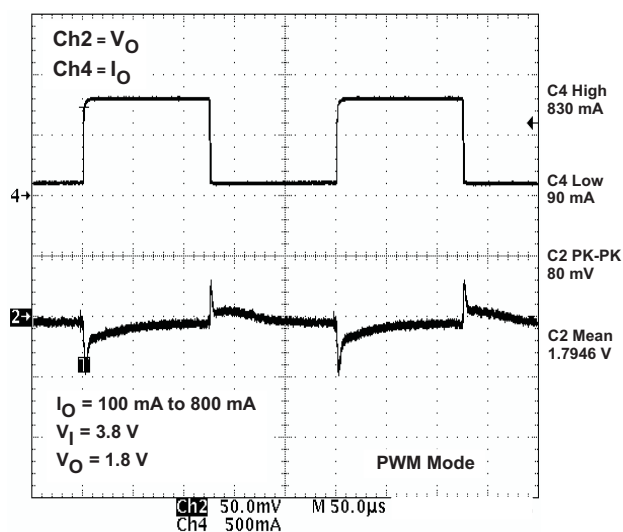


Figure 12.

VDCDC3 LOAD TRANSIENT RESPONSE

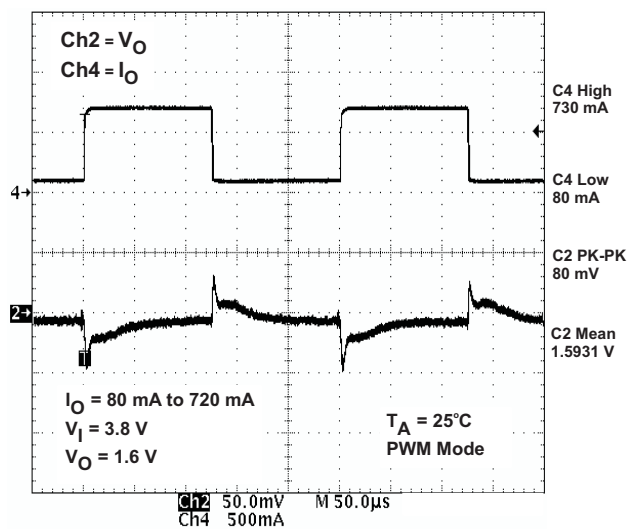


Figure 13.

VDCDC2 OUTPUT VOLTAGE RIPPLE

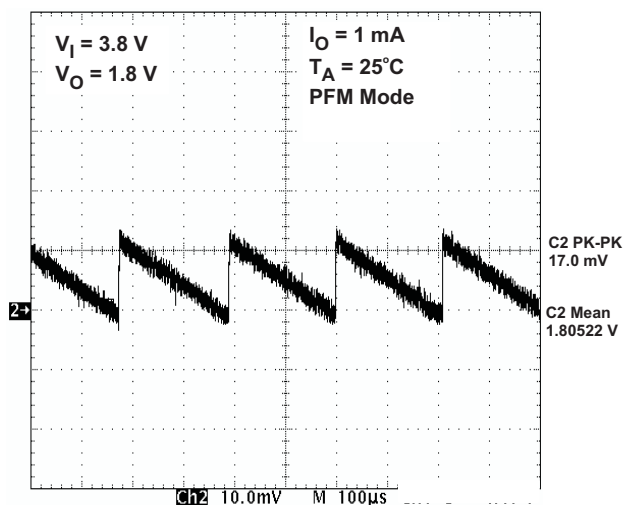


Figure 14.



VDCDC2 OUTPUT VOLTAGE RIPPLE

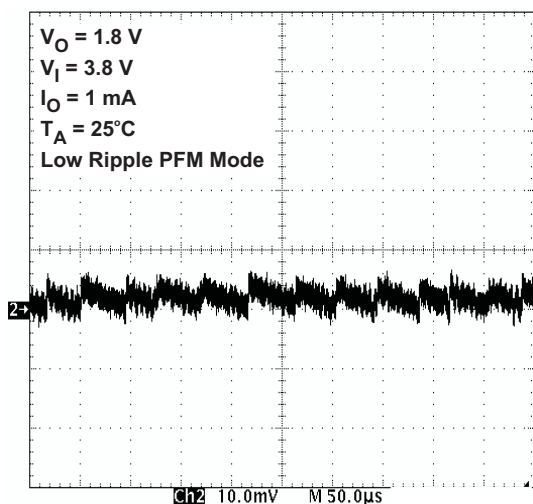


Figure 15.

VDCDC2 OUTPUT VOLTAGE RIPPLE

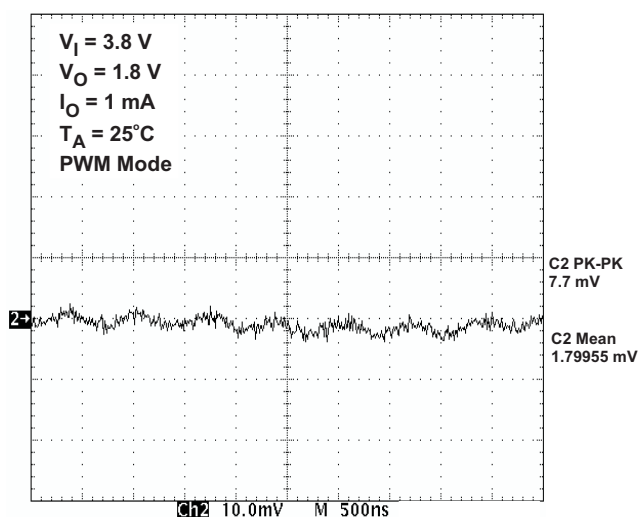


Figure 16.

STARTUP VDCDC1, VDCDC2, AND VDCDC3

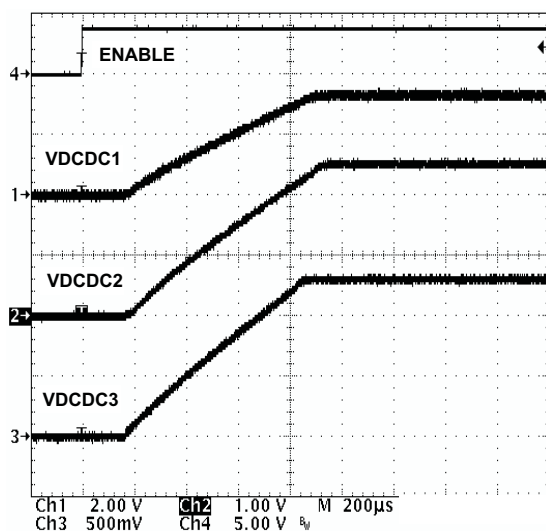


Figure 17.

STARTUP LDO1 AND LDO2

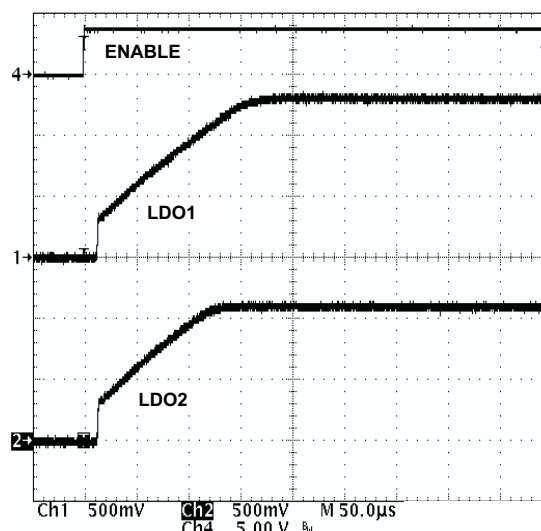


Figure 18.

LDO1 LINE TRANSIENT RESPONSE

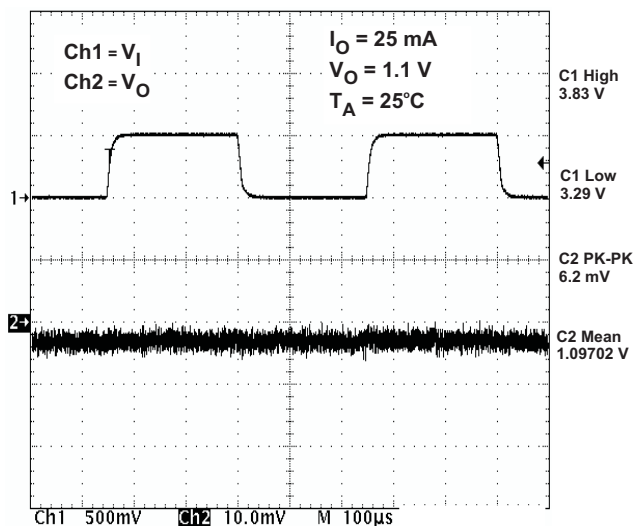


Figure 19.

LDO2 LINE TRANSIENT RESPONSE

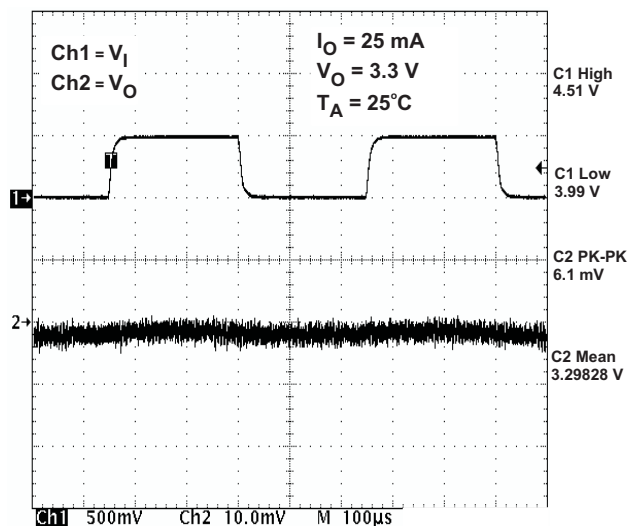


Figure 20.

VRTC LINE TRANSIENT RESPONSE

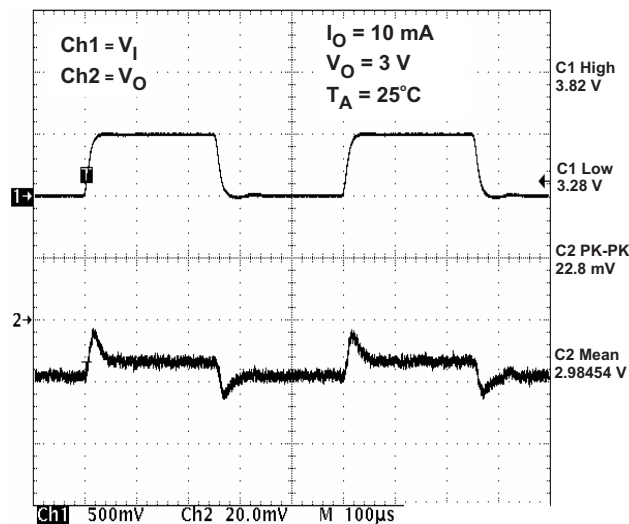


Figure 21.

LDO1 LOAD TRANSIENT RESPONSE

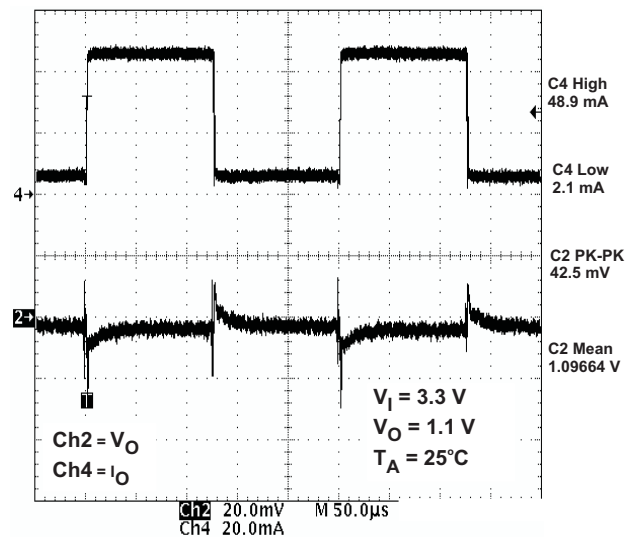


Figure 22.

LDO2 LOAD TRANSIENT RESPONSE

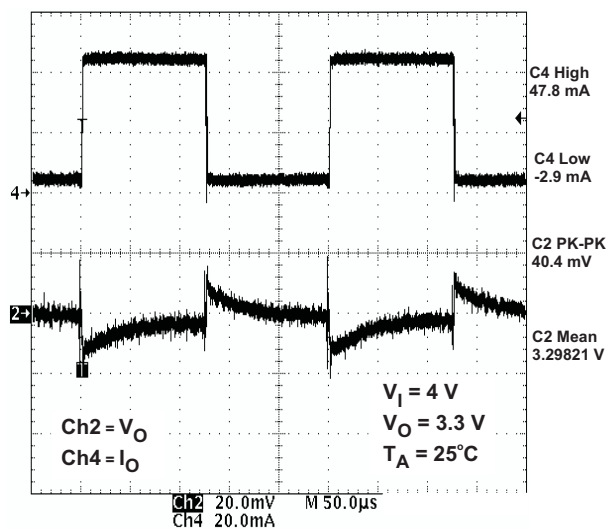


Figure 23.

VRTC LOAD TRANSIENT RESPONSE

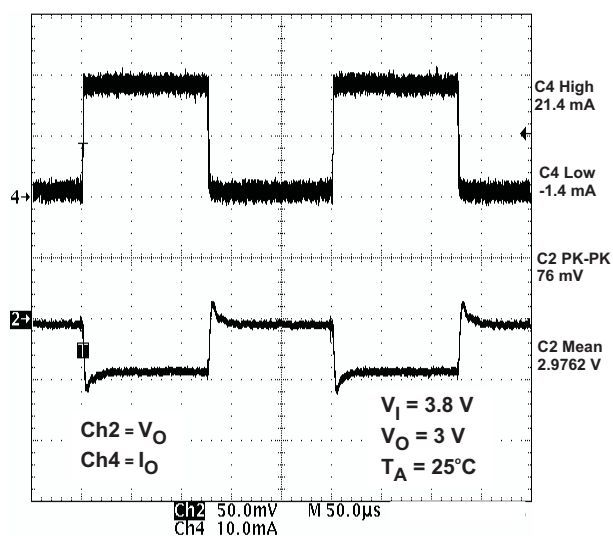


Figure 24.

## DETAILED DESCRIPTION

### VRTC OUTPUT AND OPERATION WITH OR WITHOUT BACKUP BATTERY

The VRTC pin is an always-on output, intended to supply up to 30 mA to a permanently required rail. This is the VCC\_BATT rail of the Intel® PXA270 Bulverde processor for example.

In applications using a backup battery, the backup voltage can be either directly connected to the TPS65021 VBACKUP pin if a Li-Ion cell is used, or via a boost converter (e.g. TPS61070) if a single NiMH battery is used. The voltage applied to the VBACKUP pin is fed through a PMOS switch to the VRTC pin. The TPS65021 asserts the RESPWRON signal if VRTC drops below 2.4 V. This, together with 375 mV at 30 mA drop out for the PMOS switch means that the voltage applied at VBACKUP must be greater than 2.775 V for normal system operation.

When the voltage at the VSYSIN pin exceeds 2.65 V, the path from VBACKUP to VRTC is cut, and VRTC is supplied by a similar PMOS switch from the voltage source connected to the VSYSIN input. Typically this is the VDCDC1 converter but can be any voltage source within the appropriate range.

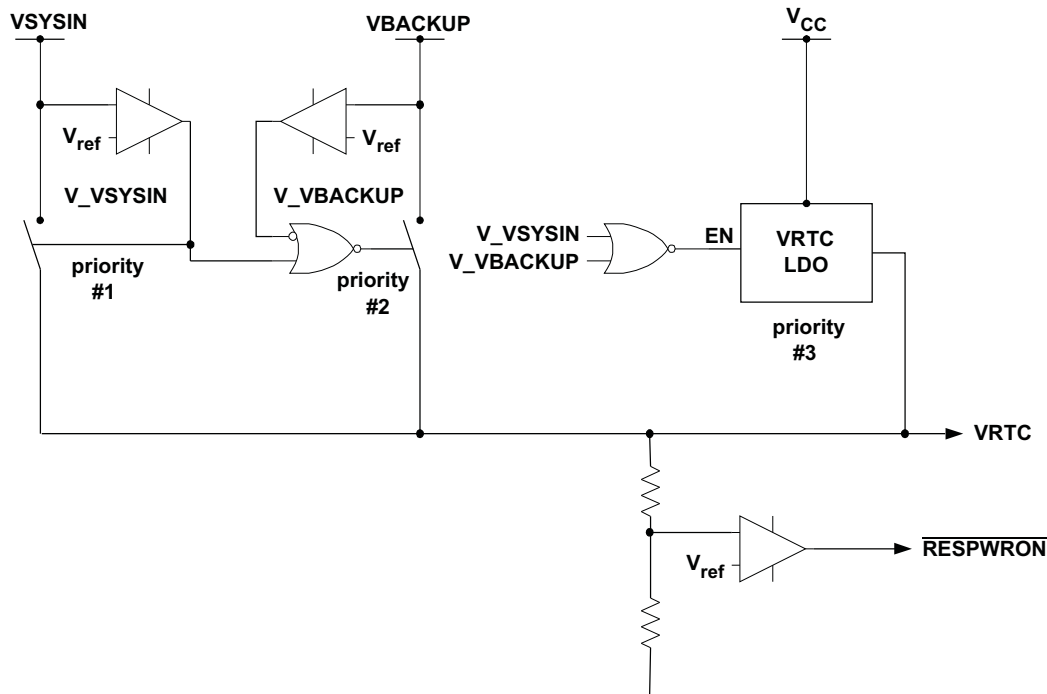
In systems where no backup battery is used, the VBACKUP pin is connected to GND. In this case, a low power LDO is enabled, supplied from VCC and capable of delivering 30 mA to the 3 V output. This LDO is disabled if the voltage at the VSYSIN input exceeds 2.65 V. VRTC is then supplied from the external source connected to this pin as previously described.

Inside TPS65021 there is a switch (Vmax switch) which selects the higher voltage between VCC and VBACKUP. This is used as the supply voltage for some basic functions. The functions powered from the output of the Vmax switch are:

- INT output
- RESPWRON output
- HOT\_RESET input
- LOW\_BATT output
- PWRFAIL output
- Enable pins for dc-dc converters, LDO1 and LDO2
- Undervoltage lockout comparator (UVLO)
- Reference system with low frequency timing oscillators
- LOW\_BATT and PWRFAIL comparators

The main 1.5-MHz oscillator, and the I<sup>2</sup>C™ interface are only powered from V<sub>CC</sub>.

## DETAILED DESCRIPTION (continued)



- A.  $V\_VSYSIN$ ,  $V\_VBACKUP$  thresholds: falling = 2.55 V, rising = 2.65 V  $\pm 3\%$
- B.  $\overline{RESPWRON}$  thresholds: falling = 2.4 V, rising = 2.52 V  $\pm 3\%$

Figure 25.

## STEP-DOWN CONVERTERS, VDCDC1, VDCDC2, and VDCDC3

The TPS65021 incorporates three synchronous step-down converters operating typically at 1.5 MHz fixed frequency pulse width modulation (PWM) at moderate to heavy load currents. At light load currents, the converters automatically enter the power save mode (PSM), and operate with pulse frequency modulation (PFM). The VDCDC1 converter is capable of delivering 1.2 A output current, the VDCDC2 converter is capable of delivering 1 A and the VDCDC3 converter is capable of delivering up to 900 mA.

The converter output voltages can be programmed via the DEFDCDC1, DEFDCDC2 and DEFDCDC3 pins. The pins can either be connected to GND, VCC, or to a resistor divider between the output voltage and GND. The VDCDC1 converter defaults to 3 V or 3.3 V depending on the DEFDCDC1 configuration pin. If DEFDCDC1 is tied to ground, the default is 3 V. If it is tied to VCC, the default is 3.3 V. When the DEFDCDC1 pin is connected to a resistor divider, the output voltage can be set in the range of 0.6 V to VINDCDC1 V. See the application information section for more details.

The VDCDC2 converter defaults to 1.8 V or 2.5 V depending on the DEFDCDC2 configuration pin. If DEFDCDC2 is tied to ground, the default is 1.8 V. If it is tied to VCC, the default is 2.5 V. When the DEFDCDC2 pin is connected to a resistor divider, the output voltage can be set in the range of 0.6 V to VINDCDC2 V.

The VDCDC3 converter defaults to 1.3 V or 1.55 V depending on the DEFDCDC3 configuration pin. If DEFDCDC3 is tied to ground the default is 1.3 V. If it is tied to VCC, the default is 1.55 V. When the DEFDCDC3 pin is connected to a resistor divider, the output voltage can be set in the range of 0.6 V to VINDCDC3 V. The core voltage can be reprogrammed via the serial interface in the range of 0.8 V to 1.6 V with a programmable slew rate. The converter is forced into PWM operation whilst any programmed voltage change is underway, whether the voltage is being increased or decreased. The DEFCORE and DEFSLEW registers are used to program the output voltage and slew rate during voltage transitions.

The step-down converter outputs (when enabled) are monitored by power good (PG) comparators, the outputs of which are available via the serial interface. The outputs of the dc-dc converters can be optionally discharged via on-chip 300- $\Omega$  resistors when the dc-dc converters are disabled.

## DETAILED DESCRIPTION (continued)

During PWM operation, the converters use a unique fast response voltage mode controller scheme with input voltage feed-forward to achieve good line and load regulation allowing the use of small ceramic input and output capacitors. At the beginning of each clock cycle initiated by the clock signal, the P-channel MOSFET switch is turned on. The inductor current ramps up until the comparator trips and the control logic turns off the switch. The current limit comparator also turns off the switch if the current limit of the P-channel switch is exceeded. After the adaptive dead time used to prevent shoot through current, the N-channel MOSFET rectifier is turned on, and the inductor current ramps down. The next cycle is initiated by the clock signal, again turning off the N-channel rectifier and turning on the P-channel switch.

The three dc-dc converters operate synchronized to each other with the VDCDC1 converter as the master. A 180° phase shift between the VDCDC1 switch turn on and the VDCDC2 and a further 90° shift to the VDCDC3 switch turn on decreases the input RMS current and smaller input capacitors can be used. This is optimized for a typical application where the VDCDC1 converter regulates a Li-Ion battery voltage of 3.7 V to 3.3 V, the VDCDC2 converter from 3.7 V to 2.5 V, and the VDCDC3 converter from 3.7 V to 1.5 V. The phase of the three converters can be changed using the CON\_CTRL register.

## POWER SAVE MODE OPERATION

As the load current decreases, the converters enter the power save mode operation. During PSM, the converters operate in a burst mode (PFM mode) with a frequency between 750 kHz and 1.5 MHz, nominal for one burst cycle. However, the frequency between different burst cycles depends on the actual load current and is typically far less than the switching frequency with a minimum quiescent current to maintain high efficiency.

In order to optimize the converter efficiency at light load, the average current is monitored and if in PWM mode the inductor current remains below a certain threshold, then PSM is entered. The typical threshold to enter PSM is calculated as follows:

$$\begin{aligned}
 I_{\text{PFMDCDC1 enter}} &= \frac{V_{\text{INDCDC1}}}{24 \, \Omega} \\
 I_{\text{PFMDCDC2 enter}} &= \frac{V_{\text{INDCDC2}}}{26 \, \Omega} \\
 I_{\text{PFMDCDC3 enter}} &= \frac{V_{\text{INDCDC3}}}{39 \, \Omega}
 \end{aligned} \tag{1}$$

During the PSM the output voltage is monitored with a comparator, and by maximum skip burst width. As the output voltage falls below the threshold, set to the nominal  $V_O$ , the P-channel switch turns on and the converter effectively delivers a constant current defined as follows.

$$\begin{aligned}
 I_{\text{PFMDCDC1 leave}} &= \frac{V_{\text{INDCDC1}}}{18 \, \Omega} \\
 I_{\text{PFMDCDC2 leave}} &= \frac{V_{\text{INDCDC2}}}{20 \, \Omega} \\
 I_{\text{PFMDCDC3 leave}} &= \frac{V_{\text{INDCDC3}}}{29 \, \Omega}
 \end{aligned} \tag{2}$$

If the load is below the delivered current then the output voltage rises until the same threshold is crossed in the other direction. All switching activity ceases, reducing the quiescent current to a minimum until the output voltage has again dropped below the threshold. The power save mode is exited, and the converter returns to PWM mode if either of the following conditions are met:

1. the output voltage drops 2% below the nominal  $V_O$  due to increasing load current
2. the PFM burst time exceeds  $16 \times 1/f_s$  (10.67  $\mu\text{s}$  typical).

## DETAILED DESCRIPTION (continued)

These control methods reduce the quiescent current to typically 14  $\mu$ A per converter, and the switching activity to a minimum, thus achieving the highest converter efficiency. Setting the comparator thresholds at the nominal output voltage at light load current results in a low output voltage ripple. The ripple depends on the comparator delay and the size of the output capacitor. Increasing capacitor values makes the output ripple tend to zero. The PSM is disabled through the I<sup>2</sup>C interface to force the individual converters to stay in fixed frequency PWM mode.

### LOW RIPPLE MODE

Setting Bit 3 in register CON-CTRL to 1 enables the low ripple mode for all of the dc-dc converters if operated in PFM mode. For an output current less than approximately 10 mA, the output voltage ripple in PFM mode is reduced, depending on the actual load current. The lower the actual output current on the converter, the lower the output ripple voltage. For an output current above 10 mA, there is only minor difference in output voltage ripple between PFM mode and low ripple PFM mode. As this feature also increases switching frequency, it is used to keep the switching frequency above the audible range in PFM mode down to a low output current.

### SOFT START

Each of the three converters has an internal soft start circuit that limits the inrush current during start-up. The soft start is realized by using a very low current to initially charge the internal compensation capacitor. The soft start time is typically 750  $\mu$ s if the output voltage ramps from 5% to 95% of the final target value. If the output is already precharged to some voltage when the converter is enabled, then this time is reduced proportionally. There is a short delay of typically 170  $\mu$ s between the converter being enabled and switching activity actually starting. This is to allow the converter to bias itself properly, to recognize if the output is precharged, and if so to prevent discharging of the output while the internal soft start ramp catches up with the output voltage.

### 100% DUTY CYCLE LOW DROPOUT OPERATION

The TPS65021 converters offer a low input to output voltage difference while still maintaining operation with the use of the 100% duty cycle mode. In this mode the P-channel switch is constantly turned on. This is particularly useful in battery-powered applications to achieve longest operation time by taking full advantage of the whole battery voltage range. The minimum input voltage required to maintain dc regulation depends on the load current and output voltage. It is calculated as:

$$V_{in\_min} = V_{out\_min} + I_{out\_max} \times (r_{DS(on)}^{max} + R_L) \quad (3)$$

with:

$I_{out\_max}$  = maximum load current (Note: ripple current in the inductor is zero under these conditions)

$r_{DS(on)}^{max}$  = maximum P-channel switch  $r_{DS(on)}$

$R_L$  = DC resistance of the inductor

$V_{out\_min}$  = nominal output voltage minus 2% tolerance limit

### ACTIVE DISCHARGE WHEN DISABLED

When the VDCDC1, VDCDC2, and VDCDC3 converters are disabled, due to an UVLO, DCDC\_EN or OVERTEMP condition, it is possible to actively pull down the outputs. This feature is disabled per default and is individually enabled via the CON\_CTRL2 register in the serial interface. When this feature is enabled, the VDCDC1, VDCDC2, and VDCDC3 outputs are discharged by a 300  $\Omega$  (typical) load which is active as long as the converters are disabled.

### POWER GOOD MONITORING

All three step-down converters and both the LDO1 and LDO2 linear regulators have power good comparators. Each comparator indicates when the relevant output voltage has dropped 10% below its target value with 5% hysteresis. The outputs of these comparators are available in the PGOODZ register via the serial interface. An interrupt is generated when any voltage rail drops below the 10% threshold. The comparators are disabled when the converters are disabled and the relevant PGOODZ register bits indicate that power is good.

## DETAILED DESCRIPTION (continued)

### LOW DROPOUT VOLTAGE REGULATORS

The low dropout voltage regulators are designed to operate well with low value ceramic input and output capacitors. They operate with input voltages down to 1.5 V. The LDOs offer a maximum dropout voltage of 300 mV at rated output current. Each LDO supports a current limit feature. Both LDOs are enabled by the LDO\_EN pin, both LDOs can be disabled or programmed via the serial interface using the REG\_CTRL and LDO\_CTRL registers. The LDOs also have reverse conduction prevention. This allows the possibility to connect external regulators in parallel in systems with a backup battery. The TPS65021 step-down and LDO voltage regulators automatically power down when the  $V_{CC}$  voltage drops below the UVLO threshold or when the junction temperature rises above 160°C.

### POWER GOOD MONITORING

Both the LDO1 and LDO2 linear regulators have power good comparators. Each comparator indicates when the relevant output voltage has dropped 10% below its target value, with 5% hysteresis. The outputs of these comparators are available in the PGOODZ register via the serial interface. An interrupt is generated when any voltage rail drops below the 10% threshold. The comparators are disabled when the LDOs are disabled and the relevant PGOODZ register bits indicate that power is good.

### UNDERVOLTAGE LOCKOUT

The undervoltage lockout circuit for the five regulators on the TPS65021 prevents the device from malfunctioning at low-input voltages and from excessive discharge of the battery. It disables the converters and LDOs. The UVLO circuit monitors the VCC pin, the threshold is set internally to 2.35 V with 5% (120 mV) hysteresis. Note that when any of the dc-dc converters are running, there is an input current at the VCC pin, which is up to 3 mA when all three converters are running in PWM mode. This current needs to be taken into consideration if an external RC filter is used at the VCC pin to remove switching noise from the TPS65021 internal analog circuitry supply.

### POWER-UP SEQUENCING

The TPS65021 power-up sequencing is designed to be entirely flexible and customer driven. This is achieved by providing separate enable pins for each switch-mode converter, and a common enable signal for the LDOs. The relevant control pins are described in [Table 2](#).

**Table 2. Control Pins and Status Outputs for DC-DC Converters**

| PIN NAME  | INPUT OUTPUT | FUNCTION  |
|-----------|--------------|---|
| DEFDCDC3  | I            | Defines the default voltage of the VDCDC3 switching converter. DEFDCDC3 = 0 defaults VDCDC3 to 1.3 V, DEFDCDC3 = VCC defaults VDCDC3 to 1.55 V.   |
| DEFDCDC2  | I            | Defines the default voltage of the VDCDC2 switching converter. DEFDCDC2 = 0 defaults VDCDC2 to 1.8 V, DEFDCDC2 = VCC defaults VDCDC2 to 2.5 V.  |
| DEFDCDC1  | I            | Defines the default voltage of the VDCDC1 switching converter. DEFDCDC1 = 0 defaults VDCDC1 to 3 V, DEFDCDC1 = VCC defaults VDCDC1 to 3.3 V.  |
| DCDC3_EN  | I            | Set DCDC3_EN = 0 to disable and DCDC3_EN = 1 to enable the VDCDC3 converter   |
| DCDC2_EN  | I            | Set DCDC2_EN = 0 to disable and DCDC2_EN = 1 to enable the VDCDC2 converter   |
| DCDC1_EN  | I            | Set DCDC1_EN = 0 to disable and DCDC1_EN = 1 to enable the VDCDC1 converter   |
| HOT_RESET | I            | The HOT_RESET pin generates a reset (RESPWRON) for the processor. HOT_RESET does not alter any TPS65021 settings except the output voltage of VDCDC3. Activating HOT_RESET sets the voltage of VDCDC3 to its default value defined with the DEFDCDC3 pin. HOT_RESET is internally de-bounced by the TPS65021. |
| RESPWRON  | O            | RESPWRON is held low when power is initially applied to the TPS65021. The VRTC voltage is monitored: RESWPRON is low when VRTC < 2.4 V and remains low for a time defined by the external capacitor at the TRESPWRON pin. RESPWRON can also be forced low by activation of the HOT_RESET pin.                 |
| TRESPWRON | I            | Connect a capacitor here to define the RESET time at the RESPWRON pin. 1 nF typically gives 100 ms.   |



## SYSTEM RESET + CONTROL SIGNALS

The  $\overline{\text{RESPWRON}}$  signal can be used as a global reset for the application. It is an open drain output. The  $\overline{\text{RESPWRON}}$  signal is generated according to the power good comparator of VRTC, and remains low for  $t_{\text{nrespwron}}$  seconds after VRTC has risen above 2.52 V (falling threshold is 2.4 V, 5% hysteresis).  $t_{\text{nrespwron}}$  is set by an external capacitor at the TRESPWRON pin. 1 nF gives typically 100 ms.  $\overline{\text{RESPWRON}}$  is also triggered by the  $\overline{\text{HOT\_RESET}}$  input. This input is internally debounced, with a filter time of typically 30 ms.

The  $\overline{\text{PWRFAIL}}$  and  $\overline{\text{LOW\_BAT}}$  signals are generated by two voltage detectors using the  $\overline{\text{PWRFAIL\_SNS}}$  and  $\overline{\text{LOWBAT\_SNS}}$  input signals. Each input signal is compared to a 1 V threshold (falling edge) with 5% (50 mV) hysteresis.

The DCDC3 converter is reset to its default output voltage defined by the DEFDCDC3 input, when  $\overline{\text{HOT\_RESET}}$  is asserted. Other I<sup>2</sup>C registers are not affected. Generally, the DCDC3 converter is set to its default voltage with one of these conditions:  $\overline{\text{HOT\_RESET}}$  active, VRTC lower than its threshold voltage, undervoltage lockout (UVLO) condition,  $\overline{\text{RESPWRON}}$  active, both DCDC3-converter AND DCDC1-converter disabled. In addition, the voltage of VDCDC3 changes to 1xxx0, if the VDCDC1 converter is disabled. Where xxx is the state before VDCDC1 was disabled.

### DEFLDO1 and DEFLDO2

These two pins are used to set the default output voltage of the two 200 mA LDOs. The digital value applied to the pins is latched during power up and determines the initial output voltage according to Table 3. The voltage of both LDOs can be changed during operation with the I<sup>2</sup>C interface as described in the interface description.

**Table 3.**

| DEFLDO2 | DEFLDO1 | VLD01  | VLD02 |
|---------|---------|--------|-------|
| 0       | 0       | 1.1 V  | 1.3 V |
| 0       | 1       | 1.5 V  | 1.3 V |
| 1       | 0       | 2.6 V  | 2.8 V |
| 1       | 1       | 3.15 V | 3.3 V |

### Interrupt Management and the $\overline{\text{INT}}$ Pin

The  $\overline{\text{INT}}$  pin combines the outputs of the PGOOD comparators from each dc-dc converter and LDOs. The  $\overline{\text{INT}}$  pin is used as a POWER\_OK pin indicating when all enabled supplies are in regulation. If the PGOODZ register is read via the serial interface, any active bits are then blocked from the  $\overline{\text{INT}}$  output pin.

Interrupts can be masked using the MASK register; default operation is not to mask any DCDC or LDO interrupts since this provides the POWER\_OK function.

## TIMING DIAGRAMS

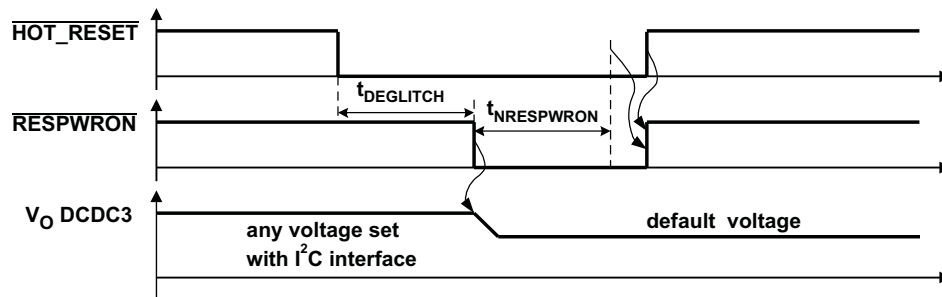


Figure 26. HOT\_RESET Timing

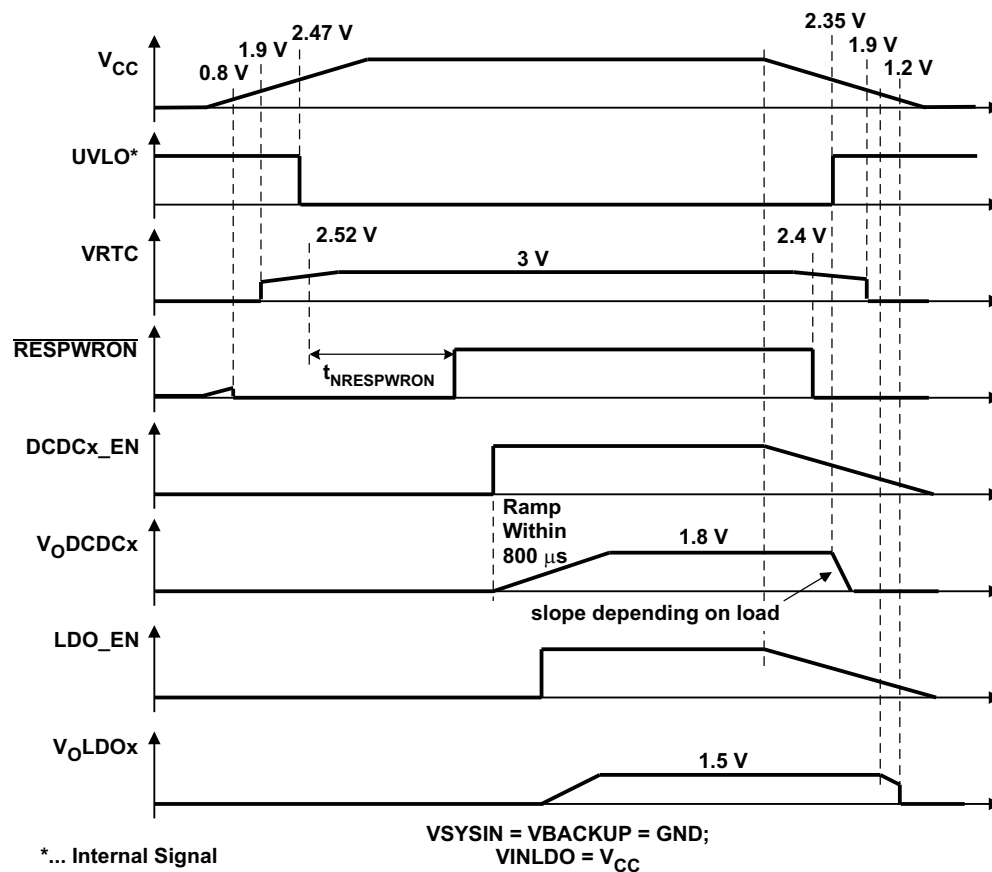


Figure 27. Power-Up and Power-Down Timing

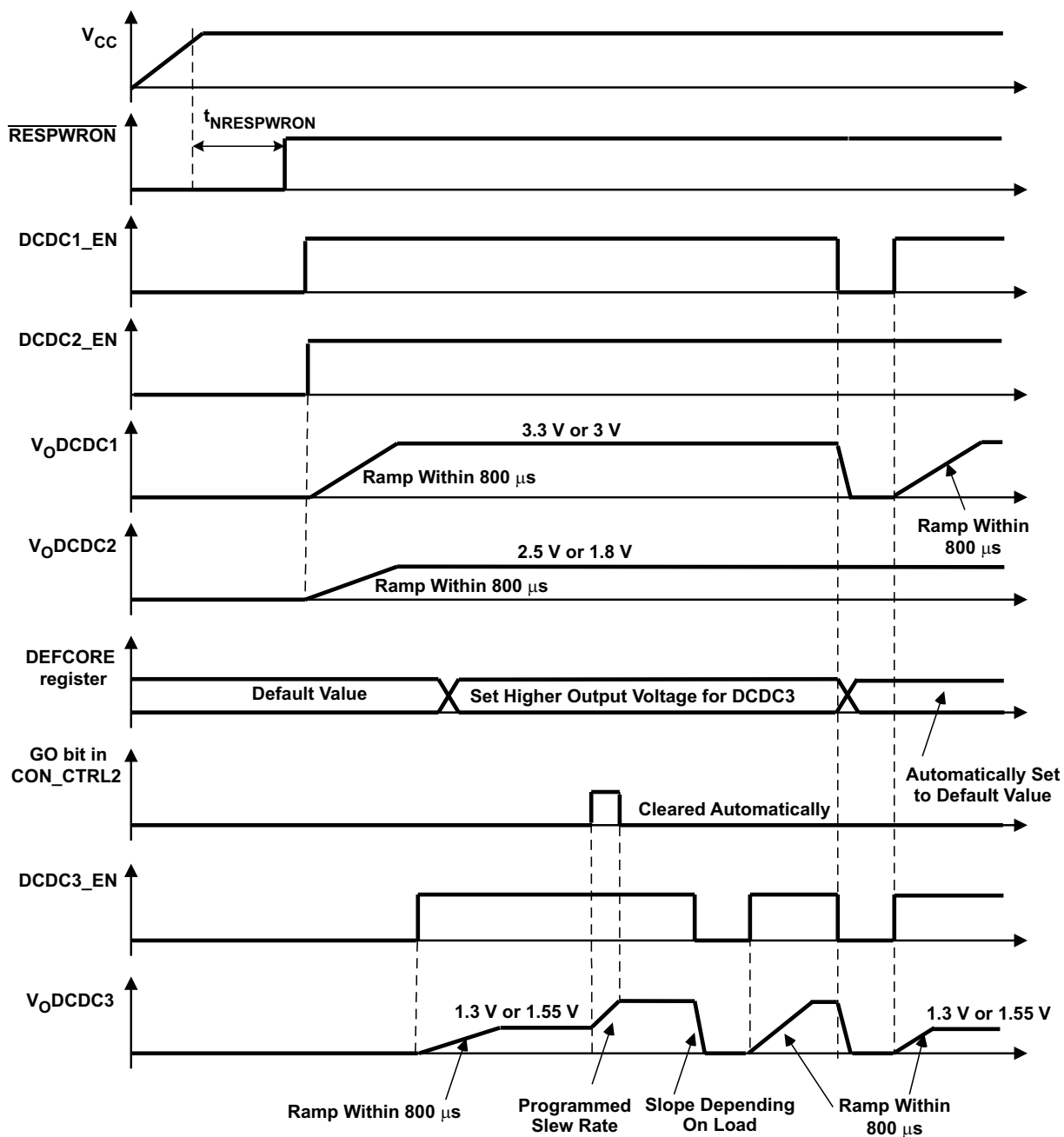


Figure 28. DVS Timing

## SERIAL INTERFACE

The serial interface is compatible with the standard and fast mode I<sup>2</sup>C specifications, allowing transfers at up to 400 kHz. The interface adds flexibility to the power supply solution, enabling most functions to be programmed to new values depending on the instantaneous application requirements and charger status to be monitored. Register contents remain intact as long as  $V_{CC}$  remains above 2 V. The TPS65021 has a 7-bit address: 1001000, other addresses are available upon contact with the factory. Attempting to read data from the register addresses not listed in this section results in FFh being read out.

For normal data transfer, DATA is allowed to change only when CLK is low. Changes when CLK is high are reserved for indicating the start and stop conditions. During data transfer, the data line must remain stable

whenever the clock line is high. There is one clock pulse per bit of data. Each data transfer is initiated with a start condition and terminated with a stop condition. When addressed, the TPS65021 device generates an acknowledge bit after the reception of each byte. The master device (microprocessor) must generate an extra clock pulse that is associated with the acknowledge bit. The TPS65021 device must pull down the DATA line during the acknowledge clock pulse so that the DATA line is a stable low during the high period of the acknowledge clock pulse. The DATA line is a stable low during the high period of the acknowledge-related clock pulse. Setup and hold times must be taken into account. During read operations, a master must signal the end of data to the slave by not generating an acknowledge bit on the last byte that was clocked out of the slave. In this case, the slave TPS65021 device must leave the data line high to enable the master to generate the stop condition

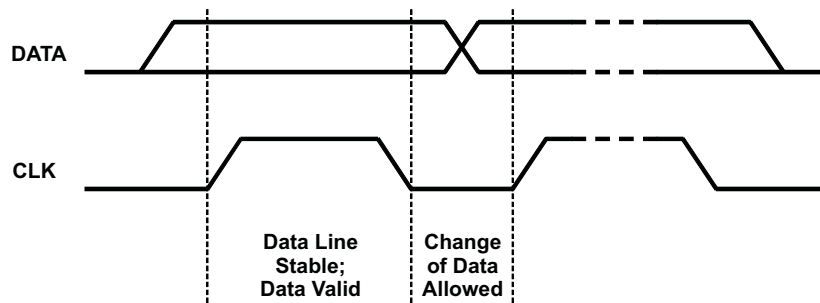


Figure 29. Bit Transfer on the Serial Interface

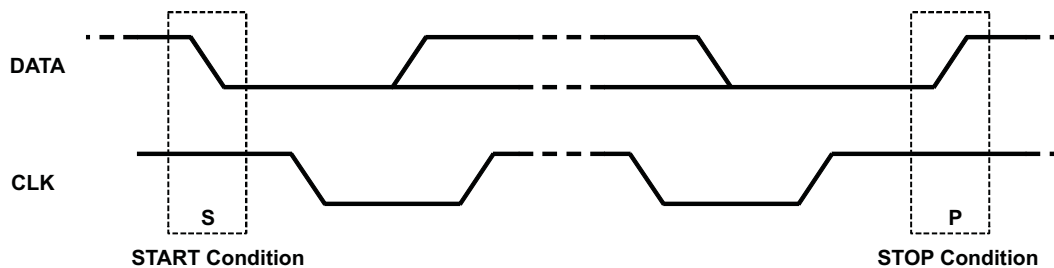
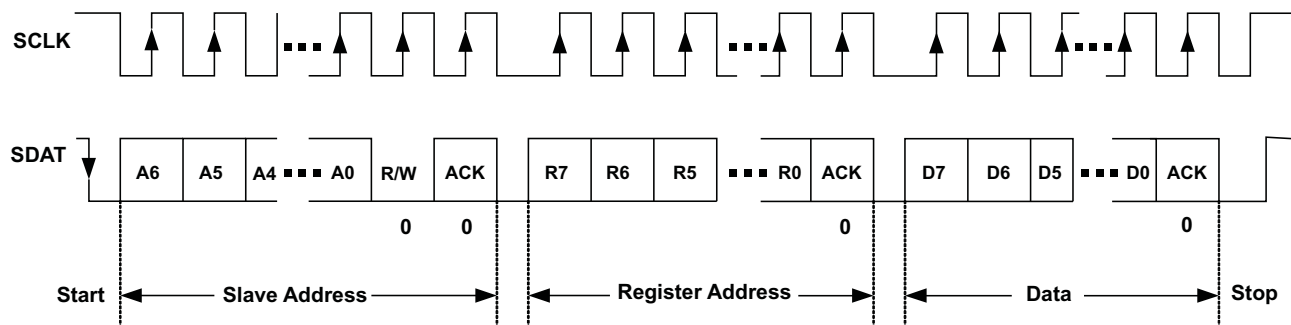


Figure 30. START and STOP Conditions



Note: SLAVE = TPS65020

Figure 31. Serial i/f WRITE to TPS65021 Device

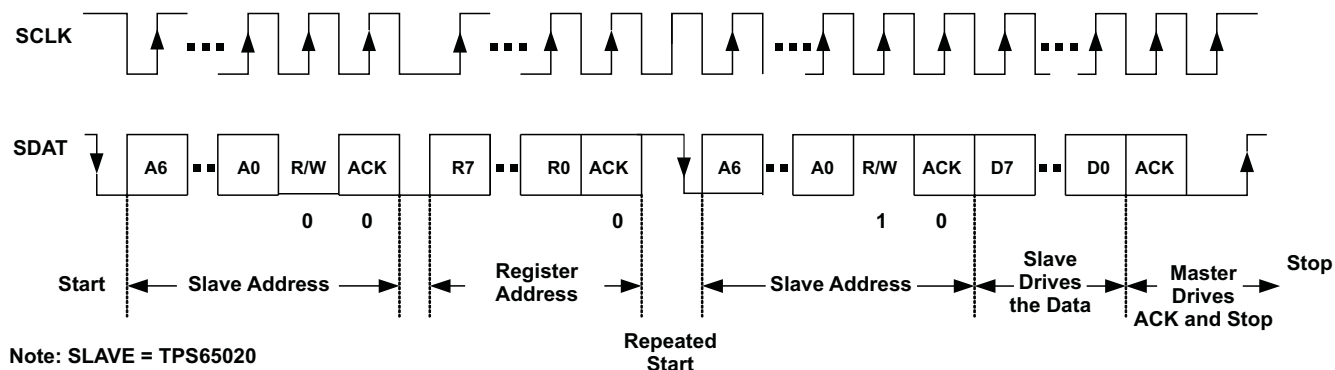


Figure 32. Serial i/f READ from TPS65021: Protocol A

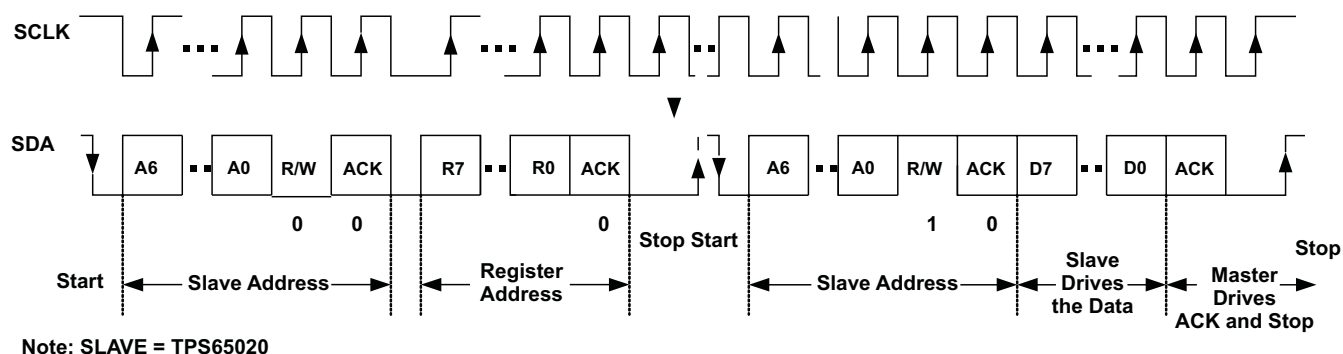


Figure 33. Serial i/f READ from TPS65021: Protocol B

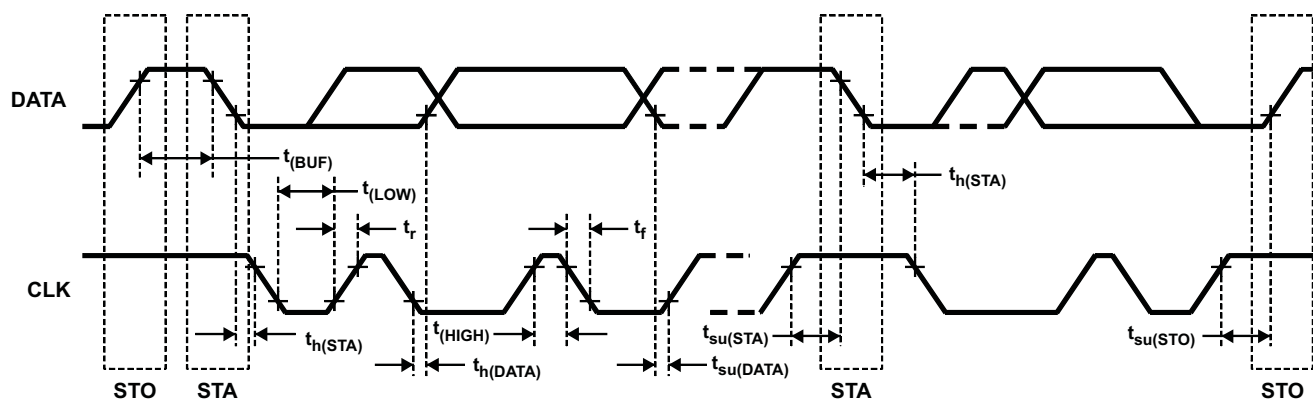


Figure 34. Serial i/f Timing Diagram

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|                |   | MIN  | MAX | UNIT |
|----------------|---|------|-----|------|
| $f_{MAX}$      | Clock frequency   |      | 400 | kHz  |
| $t_{WH(HIGH)}$ | Clock high time   | 600  |     | ns   |
| $t_{WL(LOW)}$  | Clock low time  | 1300 |     | ns   |
| $t_R$          | DATA and CLK rise time  |      | 300 | ns   |
| $t_F$          | DATA and CLK fall time  |      | 300 | ns   |
| $t_{h(STA)}$   | Hold time (repeated) START condition (after this period the first clock pulse is generated) | 600  |     | ns   |
| $t_{h(DATA)}$  | Setup time for repeated START condition   | 600  |     | ns   |
| $t_{h(DATA)}$  | Data input hold time  | 300  |     | ns   |
| $t_{su(DATA)}$ | Data input setup time   | 300  |     | ns   |
| $t_{su(STO)}$  | STOP condition setup time   | 600  |     | ns   |
| $t_{(BUF)}$    | Bus free time   | 1300 |     | ns   |

## VERSION. Register Address: 00h (read only)

| VERSION               | B7 | B6 | B5 | B4 | B3 | B2 | B1 | B0 |
|-----------------------|----|----|----|----|----|----|----|----|
| Bit name and function | 0  | 0  | 1  | 0  | 0  | 0  | 0  | 1  |
| Read/Write            | R  | R  | R  | R  | R  | R  | R  | R  |

**PGOODZ. Register Address: 01h (read only)**

| PGOODZ                   | B7       | B6       | B5            | B4            | B3            | B2          | B1          | B0 |
|--------------------------|----------|----------|---------------|---------------|---------------|-------------|-------------|----|
| Bit name and function    | PWRFAILZ | LOWBATTZ | PGOODZ VDCDC1 | PGOODZ VDCDC2 | PGOODZ VDCDC3 | PGOODZ LDO2 | PGOODZ LDO1 |    |
| Set by signal            | PWRFAIL  | LOWBATT  | PGOODZ VDCDC1 | PGOODZ VDCDC2 | PGOODZ VDCDC3 | PGOODZ LDO2 | PGOODZ LDO1 |    |
| Default value loaded by: | PWRFAILZ | LOWBATTZ | PGOOD VDCDC1  | PGOOD VDCDC2  | PGOOD VDCDC3  | PGOOD LDO2  | PGOOD LDO1  |    |
| Read/Write               | R        | R        | R             | R             | R             | R           | R           | R  |

**Bit 7 PWRFAILZ:**

0 = indicates that the PWRFAIL\_SNS input voltage is above the 1-V threshold.

1 = indicates that the PWRFAIL\_SNS input voltage is below the 1-V threshold.

**Bit 6 LOWBATTZ:**

0 = indicates that the LOWBATT\_SNS input voltage is above the 1-V threshold.

1 = indicates that the LOWBATT\_SNS input voltage is below the 1-V threshold.

**Bit 5 PGOODZ VDCDC1:**

0 = indicates that the VDCDC1 converter output voltage is within its nominal range. This bit is zero if the VDCDC1 converter is disabled.

1 = indicates that the VDCDC1 converter output voltage is below its target regulation voltage

**Bit 4 PGOODZ VDCDC2:**

0 = indicates that the VDCDC2 converter output voltage is within its nominal range. This bit is zero if the VDCDC2 converter is disabled.

1 = indicates that the VDCDC2 converter output voltage is below its target regulation voltage

**Bit 3 PGOODZ VDCDC3:**

0 = indicates that the VDCDC3 converter output voltage is within its nominal range. This bit is zero if the VDCDC3 converter is disabled and during a DVM controlled output voltage transition

1 = indicates that the VDCDC3 converter output voltage is below its target regulation voltage

**Bit 2 PGOODZ LDO2:**

0 = indicates that the LDO2 output voltage is within its nominal range. This bit is zero if LDO2 is disabled.

1 = indicates that LDO2 output voltage is below its target regulation voltage

**Bit 1 PGOODZ LDO1**

0 = indicates that the LDO1 output voltage is within its nominal range. This bit is zero if LDO1 is disabled.

1 = indicates that the LDO1 output voltage is below its target regulation voltage

**MASK. Register Address: 02h (read/write)      Default Value: C0h**

| MASK                     | B7            | B6            | B5          | B4          | B3          | B2        | B1        | B0 |
|--------------------------|---------------|---------------|-------------|-------------|-------------|-----------|-----------|----|
| Bit name and function    | MASK PWRFAILZ | MASK LOWBATTZ | MASK VDCDC1 | MASK VDCDC2 | MASK VDCDC3 | MASK LDO2 | MASK LDO1 |    |
| Default                  | 1             | 1             | 0           | 0           | 0           | 0         | 0         | 0  |
| Default value loaded by: | UVLO          | UVLO          | UVLO        | UVLO        | UVLO        | UVLO      | UVLO      |    |
| Read/Write               | R/W           | R/W           | R/W         | R/W         | R/W         | R/W       | R/W       |    |

The MASK register can be used to mask particular fault conditions from appearing at the  $\overline{\text{INT}}$  pin. MASK<n> = 1 masks PGOODZ<n>.

**REG\_CTRL. Register Address: 03h (read/write)      Default Value: FFh**

The REG\_CTRL register is used to disable or enable the power supplies via the serial interface. The contents of the register are logically AND'd with the enable pins to determine the state of the supplies. A UVLO condition resets the REG\_CTRL to 0xFF, so the state of the supplies defaults to the state of the enable pin. The REG\_CTRL bits are automatically reset to default when the corresponding enable pin is low.

| REG_CTRL                 | B7 | B6 | B5            | B4            | B3            | B2          | B1          | B0 |
|--------------------------|----|----|---------------|---------------|---------------|-------------|-------------|----|
| Bit name and function    |    |    | VDCDC1 ENABLE | VDCDC2 ENABLE | VDCDC3 ENABLE | LDO2 ENABLE | LDO1 ENABLE |    |
| Default                  | 1  | 1  | 1             | 1             | 1             | 1           | 1           | 1  |
| Set by signal            |    |    | DCDC1_ENZ     | DCDC2_ENZ     | DCDC3_ENZ     | LDO_ENZ     | LDO_ENZ     |    |
| Default value loaded by: |    |    | UVLO          | UVLO          | UVLO          | UVLO        | UVLO        |    |
| Read/Write               |    |    | R/W           | R/W           | R/W           | R/W         | R/W         |    |

**Bit 5    VDCDC1 ENABLE**

DCDC1 Enable. This bit is logically AND'd with the state of the DCDC1\_EN pin to turn on the DCDC1 converter. Reset to 1 by a UVLO condition, the bit can be written to 0 or 1 via the serial interface. The bit is reset to 1 when the pin DCDC1\_EN is pulled to GND, allowing DCDC1 to turn on when DCDC1\_EN returns high.

**Bit 4    VDCDC2 ENABLE**

DCDC2 Enable. This bit is logically AND'd with the state of the DCDC2\_EN pin to turn on the DCDC2 converter. Reset to 1 by a UVLO condition, the bit can be written to 0 or 1 via the serial interface. The bit is reset to 1 when the pin DCDC2\_EN is pulled to GND, allowing DCDC2 to turn on when DCDC2\_EN returns high.

**Bit 3    VDCDC3 ENABLE**

DCDC3 Enable. This bit is logically AND'd with the state of the DCDC3\_EN pin to turn on the DCDC3 converter. Reset to 1 by a UVLO condition, the bit can be written to 0 or 1 via the serial interface. The bit is reset to 1 when the pin DCDC3\_EN is pulled to GND, allowing DCDC3 to turn on when DCDC3\_EN returns high.

**Bit 2    LDO2 ENABLE**

LDO2 Enable. This bit is logically AND'd with the state of the LDO2\_EN pin to turn on LDO2. Reset to 1 by a UVLO condition, the bit can be written to 0 or 1 via the serial interface. The bit is reset to 1 when the pin LDO\_EN is pulled to GND, allowing LDO2 to turn on when LDO\_EN returns high.

**Bit 1    LDO1 ENABLE**

LDO1 Enable. This bit is logically AND'd with the state of the LDO1\_EN pin to turn on LDO1. Reset to 1 by a UVLO condition, the bit can be written to 0 or 1 via the serial interface. The bit is reset to 1 when the pin LDO\_EN is pulled to GND, allowing LDO1 to turn on when LDO\_EN returns high.



**CON\_CTRL. Register Address: 04h (read/write)      Default Value: B1h**

| CON_CTRL                 | B7           | B6           | B5           | B4           | B3         | B2         | B1         | B0         |
|--------------------------|--------------|--------------|--------------|--------------|------------|------------|------------|------------|
| Bit name and function    | DCDC2 PHASE1 | DCDC2 PHASE0 | DCDC3 PHASE1 | DCDC3 PHASE0 | LOW RIPPLE | FPWM DCDC2 | FPWM DCDC1 | FPWM DCDC3 |
| Default                  | 1            | 0            | 1            | 1            | 0          | 0          | 0          | 1          |
| Default value loaded by: | UVLO         | UVLO         | UVLO         | UVLO         | UVLO       | UVLO       | UVLO       | UVLO       |
| Read/Write               | R/W          | R/W          | R/W          | R/W          | R/W        | R/W        | R/W        | R/W        |

The CON\_CTRL register is used to force any or all of the converters into forced PWM operation, when low output voltage ripple is vital. It is also used to control the phase shift between the three converters in order to minimize the input rms current, hence reduce the required input blocking capacitance. The DCDC1 converter is taken as the reference and consequently has a fixed zero phase shift.

| CON_CTRL<7:6> | DCDC2 CONVERTER<br>DELAYED BY |  | CON_CTRL<5:4> | DCDC3 CONVERTER<br>DELAYED BY |
|---------------|-------------------------------|--|---------------|-------------------------------|
| 00            | zero                          |  | 00            | zero                          |
| 01            | 1/4 cycle                     |  | 01            | 1/4 cycle                     |
| <b>10</b>     | <b>cycle</b>                  |  | 10            | cycle                         |
| 11            | 3/4 cycle                     |  | <b>11</b>     | <b>3/4 cycle</b>              |

**Bit 3    LOW RIPPLE:**

- 0 =    PFM mode operation optimized for high efficiency for all converters
- 1 =    PFM mode operation optimized for low output voltage ripple for all converters

**Bit 2    FPWM DCDC2:**

- 0 =    DCDC2 converter operates in PWM / PFM mode
- 1 =    DCDC2 converter is forced into fixed frequency PWM mode

**Bit 1    FPWM DCDC1:**

- 0 =    DCDC1 converter operates in PWM / PFM mode
- 1 =    DCDC1 converter is forced into fixed frequency PWM mode

**Bit 0    FPWM DCDC3:**

- 0 =    DCDC3 converter operates in PWM / PFM mode
- 1 =    DCDC3 converter is forced into fixed frequency PWM mode

**CON\_CTRL2. Register Address: 05h (read/write)      Default Value: 40h**

| CON_CTRL2                | B7          | B6               | B5 | B4 | B3 | B2              | B1              | B0              |
|--------------------------|-------------|------------------|----|----|----|-----------------|-----------------|-----------------|
| Bit name and function    | GO          | Core adj allowed |    |    |    | DCDC2 discharge | DCDC1 discharge | DCDC3 discharge |
| Default                  | 0           | 1                | 0  | 0  | 0  | 0               | 0               | 0               |
| Default value loaded by: | UVLO + DONE | UVLO             |    |    |    | UVLO            | UVLO            | UVLO            |
| Read/Write               | R/W         | R/W              |    |    |    | R/W             | R/W             | R/W             |

The CON\_CTRL2 register can be used to take control the inductive converters.

**Bit 7      GO:**

- 0 = no change in the output voltage for the DCDC3 converter
- 1 = the output voltage of the DCDC3 converter is changed to the value defined in DEFCORE with the slew rate defined in DEFSLEW. This bit is automatically cleared when the DVM transition is complete. The transition is considered complete in this case when the desired output voltage code has been reached, not when the VDCDC3 output voltage is actually in regulation at the desired voltage.

**Bit 6      CORE ADJ Allowed:**

- 0 = the output voltage is set with the I<sup>2</sup>C register
- 1 = DEFDCDC3 is either connected to GND or VCC or an external voltage divider. When connected to GND or VCC, VDCDC3 defaults to 1.3 V or 1.55 V respectively at start-up

- Bit 2–0      0 =** the output capacitor of the associated converter is not actively discharged when the converter is disabled
- 1 =** the output capacitor of the associated converter is actively discharged when the converter is disabled. This decreases the fall time of the output voltage at light load

**DEFCORE. Register Address: 06h (read/write) Default Value: 14h/1Eh**

| DEFCORE                  | B7 | B6 | B5 | B4       | B3       | B2       | B1       | B0       |
|--------------------------|----|----|----|----------|----------|----------|----------|----------|
| Bit name and function    |    |    |    | CORE4    | CORE3    | CORE2    | CORE1    | CORE0    |
| Default                  | 0  | 0  | 0  | 1        | DEFDCDC3 | 1        | DEFDCDC3 | 0        |
| Default value loaded by: |    |    |    | RESET(1) | RESET(1) | RESET(1) | RESET(1) | RESET(1) |
| Read/Write               |    |    |    | R/W      | R/W      | R/W      | R/W      | R/W      |

RESET(1): DEFCORE is reset to its default value by one of these events:

- undervoltage lockout (UVLO)
- DCDC1 AND DCDC3 disabled
- $\overline{\text{HOT\_RESET}}$  pulled low
- $\overline{\text{RESPWRON}}$  active
- VRTC below threshold

| CORE4 | CORE3 | CORE2 | CORE1 | CORE0 | VDCDC3  | CORE4 | CORE3 | CORE2 | CORE1 | CORE0 | VDCDC3  |
|-------|-------|-------|-------|-------|---------|-------|-------|-------|-------|-------|---------|
| 0     | 0     | 0     | 0     | 0     | 0.8 V   | 1     | 0     | 0     | 0     | 0     | 1.2 V   |
| 0     | 0     | 0     | 0     | 1     | 0.825 V | 1     | 0     | 0     | 0     | 1     | 1.225 V |
| 0     | 0     | 0     | 1     | 0     | 0.85 V  | 1     | 0     | 0     | 1     | 0     | 1.25 V  |
| 0     | 0     | 0     | 1     | 1     | 0.875 V | 1     | 0     | 0     | 1     | 1     | 1.275 V |
| 0     | 0     | 1     | 0     | 0     | 0.9 V   | 1     | 0     | 1     | 0     | 0     | 1.3 V   |
| 0     | 0     | 1     | 0     | 1     | 0.925 V | 1     | 0     | 1     | 0     | 1     | 1.325 V |
| 0     | 0     | 1     | 1     | 0     | 0.95 V  | 1     | 0     | 1     | 1     | 0     | 1.35 V  |
| 0     | 0     | 1     | 1     | 1     | 0.975 V | 1     | 0     | 1     | 1     | 1     | 1.375 V |
| 0     | 1     | 0     | 0     | 0     | 1 V     | 1     | 1     | 0     | 0     | 0     | 1.4 V   |
| 0     | 1     | 0     | 0     | 1     | 1.025 V | 1     | 1     | 0     | 0     | 1     | 1.425 V |
| 0     | 1     | 0     | 1     | 0     | 1.05 V  | 1     | 1     | 0     | 1     | 0     | 1.45 V  |
| 0     | 1     | 0     | 1     | 1     | 1.075 V | 1     | 1     | 0     | 1     | 1     | 1.475 V |
| 0     | 1     | 1     | 0     | 0     | 1.1 V   | 1     | 1     | 1     | 0     | 0     | 1.5 V   |
| 0     | 1     | 1     | 0     | 1     | 1.125 V | 1     | 1     | 1     | 0     | 1     | 1.525 V |
| 0     | 1     | 1     | 1     | 0     | 1.15 V  | 1     | 1     | 1     | 1     | 0     | 1.55 V  |
| 0     | 1     | 1     | 1     | 1     | 1.175 V | 1     | 1     | 1     | 1     | 1     | 1.6 V   |

**DEFSLEW. Register Address: 07h (read/write) Default Value: 06h**

| DEFSLEW                  | B7 | B6 | B5 | B4 | B3 | B2    | B1    | B0    |
|--------------------------|----|----|----|----|----|-------|-------|-------|
| Bit name and function    |    |    |    |    |    | SLEW2 | SLEW1 | SLEW0 |
| Default                  |    |    |    |    |    | 1     | 1     | 0     |
| Default value loaded by: |    |    |    |    |    | UVLO  | UVLO  | UVLO  |
| Read/Write               |    |    |    |    |    | R/W   | R/W   | R/W   |

| SLEW2 | SLEW1 | SLEW0 | VDCDC3 SLEW RATE |
|-------|-------|-------|------------------|
| 0     | 0     | 0     | 0.15 mV/μs       |
| 0     | 0     | 1     | 0.3 mV/μs        |
| 0     | 1     | 0     | 0.6 mV/μs        |
| 0     | 1     | 1     | 1.2 mV/μs        |
| 1     | 0     | 0     | 2.4 mV/μs        |
| 1     | 0     | 1     | 4.8 mV/μs        |
| 1     | 1     | 0     | 9.6 mV/μs        |
| 1     | 1     | 1     | Immediate        |

**LDO\_CTRL. Register Address: 08h (read/write)****Default Value: set with DEFLDO1 and DEFLDO2**

| LDO_CTRL                 | B7 | B6      | B5      | B4      | B3 | B2      | B1      | B0      |
|--------------------------|----|---------|---------|---------|----|---------|---------|---------|
| Bit name and function    |    | LDO2_2  | LDO2_1  | LDO2_0  |    | LDO1_2  | LDO1_1  | LDO1_0  |
| Default                  |    | DEFLDOx | DEFLDOx | DEFLDOx |    | DEFLDOx | DEFLDOx | DEFLDOx |
| Default value loaded by: |    | UVLO    | UVLO    | UVLO    |    | UVLO    | UVLO    | UVLO    |
| Read/Write               |    | R/W     | R/W     | R/W     |    | R/W     | R/W     | R/W     |

The LDO\_CTRL registers can be used to set the output voltage of LDO1 and LDO2.

The default voltage is set with DEFLDO1 and DEFLDO2 pins as described in [Table 3](#).

| LDO1_2 | LDO1_1 | LDO1_0 | LDO1 OUTPUT VOLTAGE |  | LDO2_2 | LDO2_1 | LDO2_0 | LDO2 OUTPUT VOLTAGE |
|--------|--------|--------|---------------------|--|--------|--------|--------|---------------------|
| 0      | 0      | 0      | 1 V                 |  | 0      | 0      | 0      | 1.05 V              |
| 0      | 0      | 1      | 1.1 V               |  | 0      | 0      | 1      | 1.2 V               |
| 0      | 1      | 0      | 1.35 V              |  | 0      | 1      | 0      | 1.3 V               |
| 0      | 1      | 1      | 1.5 V               |  | 0      | 1      | 1      | 1.8 V               |
| 1      | 0      | 0      | 2.2 V               |  | 1      | 0      | 0      | 2.5 V               |
| 1      | 0      | 1      | 2.6 V               |  | 1      | 0      | 1      | 2.8 V               |
| 1      | 1      | 0      | 2.85 V              |  | 1      | 1      | 0      | 3 V                 |
| 1      | 1      | 1      | 3.15 V              |  | 1      | 1      | 1      | 3.3 V               |

**DESIGN PROCEDURE****Inductor Selection for the DC-DC Converters**

Each of the converters in the TPS65021 typically use a 3.3 µH output inductor. Larger or smaller inductor values are used to optimize the performance of the device for specific operation conditions. The selected inductor has to be rated for its dc resistance and saturation current. The dc resistance of the inductance influences directly the efficiency of the converter. Therefore, an inductor with lowest dc resistance should be selected for highest efficiency.

For a fast transient response, a 2.2-µH inductor in combination with a 22-µF output capacitor is recommended.

[Equation 4](#) calculates the maximum inductor current under static load conditions. The saturation current of the inductor should be rated higher than the maximum inductor current as calculated with [Equation 4](#). This is needed because during heavy load transient the inductor current rises above the value calculated under [Equation 4](#).

$$\Delta I_L = V_{out} \times \frac{1 - \frac{V_{out}}{V_{in}}}{L \times f} \quad (4)$$

$$I_{Lmax} = I_{outmax} + \frac{\Delta I_L}{2} \quad (5)$$

with:

f = Switching Frequency (1.5 MHz typical)

L = Inductor Value

ΔI<sub>L</sub> = Peak-to-Peak inductor ripple current

I<sub>LMAX</sub> = Maximum Inductor current

The highest inductor current occurs at maximum Vin.

Open core inductors have a soft saturation characteristic, and they can usually handle higher inductor currents versus a comparable shielded inductor.

A more conservative approach is to select the inductor current rating just for the maximum switch current of the TPS65021 (2 A for the VDCDC1 and VDCDC2 converters, and 1.5 A for the VDCDC3 converter). The core material from inductor to inductor differs and has an impact on the efficiency especially at high switching frequencies.

See [Table 4](#) and the typical applications for possible inductors.

**Table 4. Tested Inductors**

| DEVICE          | INDUCTOR VALUE | TYPE              | COMPONENT SUPPLIER |
|-----------------|----------------|-------------------|--------------------|
| DCDC3 converter | 3.3 µH         | CDRH2D14NP-3R3    | Sumida             |
|                 | 3.3 µH         | LPS3010-332       | Coilcraft          |
|                 | 3.3 µH         | VLF4012AT-3R3M1R3 | TDK                |
|                 | 2.2 µH         | VLF4012AT-2R2M1R5 | TDK                |
| DCDC2 converter | 3.3 µH         | CDRH2D18/HPNP-3R3 | Sumida             |
|                 | 3.3 µH         | VLF4012AT-3R3M1R3 | TDK                |
|                 | 2.2 µH         | VLFC4020-2R2      | TDK                |
| DCDC1 converter | 3.3 µH         | CDRH3D14/HPNP-3R2 | Sumida             |
|                 | 3.3 µH         | CDRH4D28C-3R2     | Sumida             |
|                 | 3.3 µH         | MSS5131-332       | Coilcraft          |
|                 | 2.2 µH         | VLFC4020-2R2      | TDK                |

## Output Capacitor Selection

The advanced Fast Response voltage mode control scheme of the inductive converters implemented in the TPS65021 allow the use of small ceramic capacitors with a typical value of 10 µF for each converter without having large output voltage under and overshoots during heavy load transients. Ceramic capacitors having low ESR values have the lowest output voltage ripple and are recommended. See [Table 5](#) for recommended components.

If ceramic output capacitors are used, the capacitor RMS ripple current rating always meets the application requirements. Just for completeness, the RMS ripple current is calculated as:

$$I_{RMSout} = V_{out} \times \frac{1 - \frac{V_{out}}{V_{in}}}{L \times f} \times \frac{1}{2 \times \sqrt{3}} \quad (6)$$

At nominal load current, the inductive converters operate in PWM mode. The overall output voltage ripple is the sum of the voltage spike caused by the output capacitor ESR plus the voltage ripple caused by charging and discharging the output capacitor:

$$\Delta V_{out} = V_{out} \times \frac{1 - \frac{V_{out}}{V_{in}}}{L \times f} \times \left( \frac{1}{8 \times C_{out} \times f} + ESR \right) \quad (7)$$

Where the highest output voltage ripple occurs at the highest input voltage  $V_{in}$ .

At light load currents, the converters operate in PSM and the output voltage ripple is dependent on the output capacitor value. The output voltage ripple is set by the internal comparator delay and the external capacitor. The typical output voltage ripple is less than 1% of the nominal output voltage.

## Input Capacitor Selection

Because of the nature of the buck converter having a pulsating input current, a low ESR input capacitor is required for best input voltage filtering and minimizing the interference with other circuits caused by high input voltage spikes. Each dc-dc converter requires a 10- $\mu$ F ceramic input capacitor on its input pin VINDCDCx. The input capacitor is increased without any limit for better input voltage filtering. The VCC pin is separated from the input for the dc-dc converters. A filter resistor of up to 10R and a 1- $\mu$ F capacitor is used for decoupling the VCC pin from switching noise. Note that the filter resistor may affect the UVLO threshold since up to 3 mA can flow via this resistor into the VCC pin when all converters are running in PWM mode.

**Table 5. Possible Capacitors**

| CAPACITOR VALUE | CASE SIZE | COMPONENT SUPPLIER        | COMMENTS |
|-----------------|-----------|---------------------------|----------|
| 22 $\mu$ F      | 1206      | TDK C3216X5R0J226M        | Ceramic  |
| 22 $\mu$ F      | 1206      | Taiyo Yuden JMK316BJ226ML | Ceramic  |
| 22 $\mu$ F      | 0805      | TDK C2012X5R0J226MT       | Ceramic  |
| 22 $\mu$ F      | 0805      | Taiyo Yuden JMK212BJ226MG | Ceramic  |
| 10 $\mu$ F      | 0805      | Taiyo Yuden JMK212BJ106M  | Ceramic  |
| 10 $\mu$ F      | 0805      | TDK C2012X5R0J106M        | Ceramic  |

## Output Voltage Selection

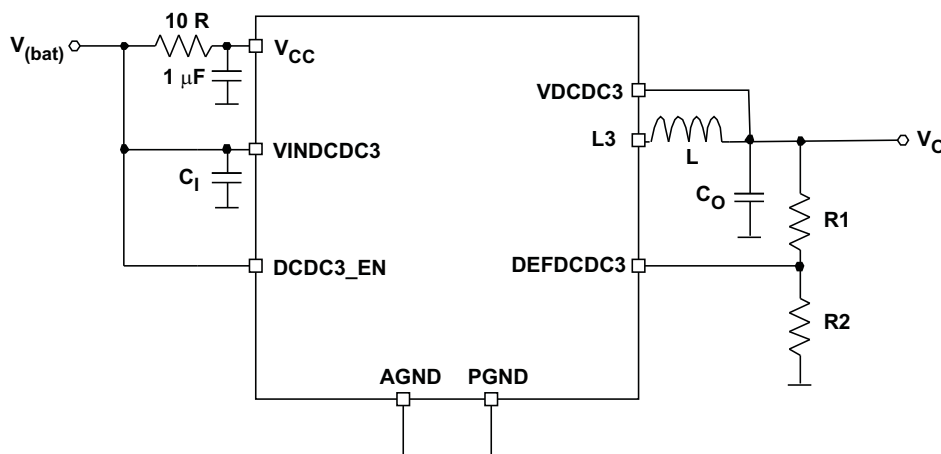
The DEFDCDC1, DEFDCDC2, and DEFDCDC3 pins are used to set the output voltage for each step-down converter. See [Table 6](#) for the default voltages if the pins are pulled to GND or to VCC. If a different voltage is needed, an external resistor divider can be added to the DEFDCDCx pin as shown in [Figure 35](#).

The output voltage of VDCDC3 is set with the I<sup>2</sup>C interface. If the voltage is changed from the default, using the DEFDCDC3 register, the output voltage only depends on the register value. Any resistor divider at DEFDCDC3 does not change the voltage set with the register.

**Table 6.**

| PIN      | LEVEL | DEFAULT OUTPUT VOLTAGE |
|----------|-------|------------------------|
| DEFDCDC1 | VCC   | 3.3 V                  |
|          | GND   | 3 V                    |
| DEFDCDC2 | VCC   | 2.5 V                  |
|          | GND   | 1.8 V                  |
| DEFDCDC3 | VCC   | 1.55 V                 |
|          | GND   | 1.3 V                  |

Using an external resistor divider at DEFDCDCx:



**Figure 35. External Resistor Divider**

When a resistor divider is connected to DEFDCDCx, the output voltage can be set from 0.6 V up to the input voltage  $V_{(bat)}$ . The total resistance ( $R1+R2$ ) of the voltage divider should be kept in the 1-MR range in order to maintain a high efficiency at light load.

$$V_{(DEFDCDCx)} = 0.6 \text{ V}$$

$$V_{OUT} = V_{DEFDCDCx} \times \frac{R1 + R2}{R2} \quad R1 = R2 \times \left( \frac{V_{OUT}}{V_{DEFDCDCx}} \right) - R2 \quad (8)$$

### VRTC Output

The VRTC output is typically connected to the Vcc\_Batt pin of a Intel® PXA270 processor. During power-up of the processor, the TPS65021 internally switches from the LDO or the backup battery to the system voltage connected at the VSYSIN pin (see [Figure 25](#)). It is recommended that a 4.7-μF (minimum) capacitor be added to the VRTC pin.

### LDO1 and LDO2

The LDOs in the TPS65021 are general-purpose LDOs which are stable using ceramics capacitors. The minimum output capacitor required is 2.2 μF. The LDOs output voltage can be changed to different voltages between 1 V and 3.3 V using the I<sup>2</sup>C interface. Therefore, they can also be used as general-purpose LDOs in applications powering processors different from PXA270. The supply voltage for the LDOs needs to be connected to the VINLDO pin, giving the flexibility to connect the lowest voltage available in the system and provides the highest efficiency.

### TRESPWRON

This is the input to a capacitor that defines the reset delay time after the voltage at VRTC rises above 2.52 V. The timing is generated by charging and discharging the capacitor with a current of 2 μA between a threshold of 0.25 V and 1 V for 128 cycles. A 1-nF capacitor gives a delay time of 100 ms.

$$t_{(reset)} = 2 \times 128 \times \left( \frac{(1 \text{ V} - 0.25 \text{ V}) \times C_{(reset)}}{2 \mu\text{A}} \right) \quad (9)$$

Where:

$t_{(reset)}$  is the reset delay time

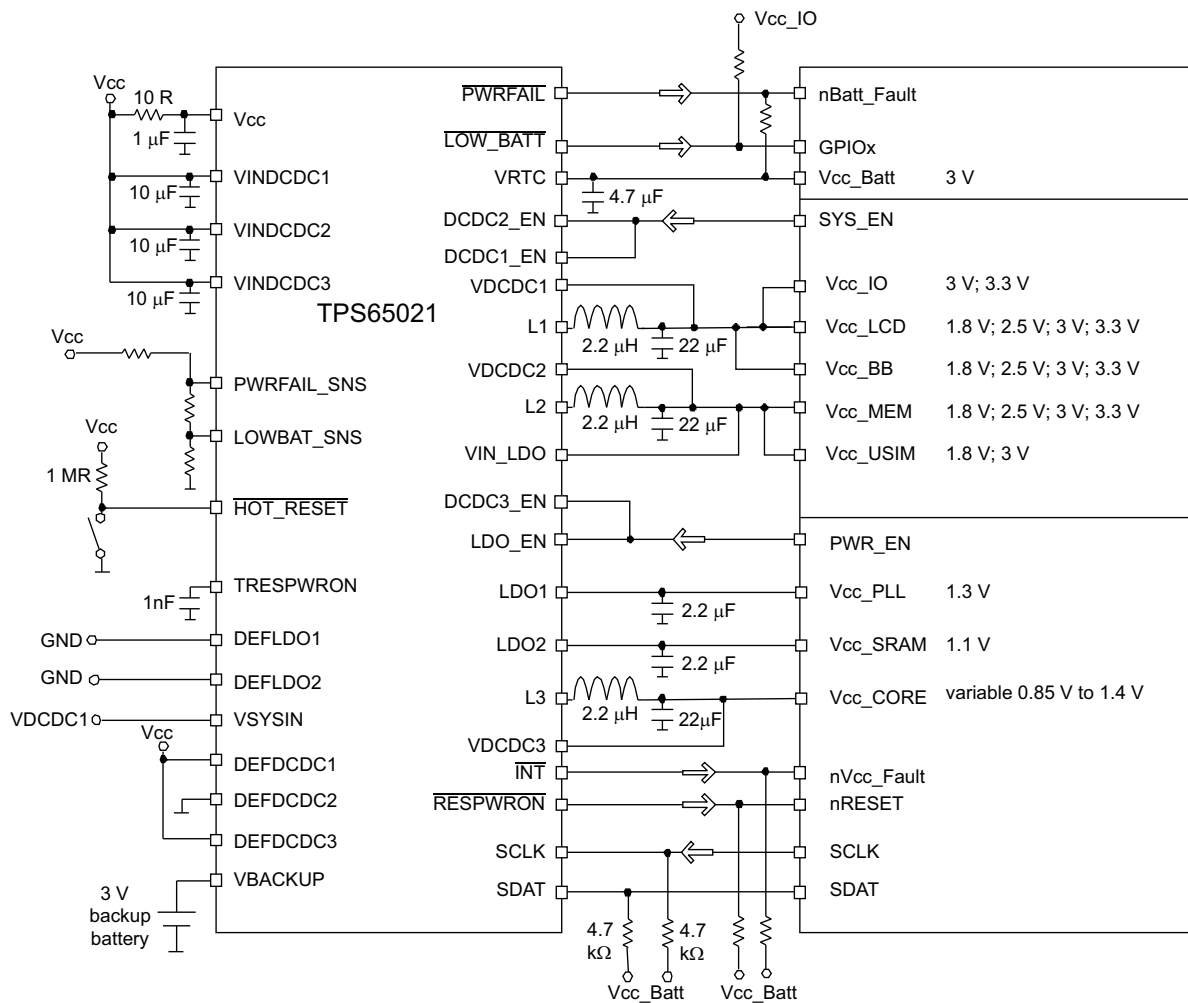
$C_{(reset)}$  is the capacitor connected to the TRESPWRON pin

### V<sub>CC</sub>-Filter

An RC filter connected at the VCC input is used to keep noise from the internal supply for the bandgap and other analog circuitry. A typical value of 10 R and 1 μF is used to filter the switching spikes, generated by the dc-dc converters. A larger resistor than 10 R should not be used because the current into VCC of up to 3 mA causes a voltage drop at the resistor causing the undervoltage lockout circuitry connected at VCC internally to switch off too early.

## APPLICATION INFORMATION

### TYPICAL CONFIGURATION FOR THE Intel® PXA270 BULVERDE PROCESSOR





**PACKAGING INFORMATION**

| Orderable Device | Status <sup>(1)</sup> | Package Type | Package Drawing | Pins | Package Qty | Eco Plan <sup>(2)</sup> | Lead/Ball Finish | MSL Peak Temp <sup>(3)</sup> |
|------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|------------------|------------------------------|
| TPS65021RHAR     | ACTIVE                | VQFN         | RHA             | 40   | 2500        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-3-260C-168 HR          |
| TPS65021RHARG4   | ACTIVE                | VQFN         | RHA             | 40   | 2500        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-3-260C-168 HR          |
| TPS65021RHAT     | ACTIVE                | VQFN         | RHA             | 40   | 250         | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-3-260C-168 HR          |
| TPS65021RHATG4   | ACTIVE                | VQFN         | RHA             | 40   | 250         | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-3-260C-168 HR          |

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

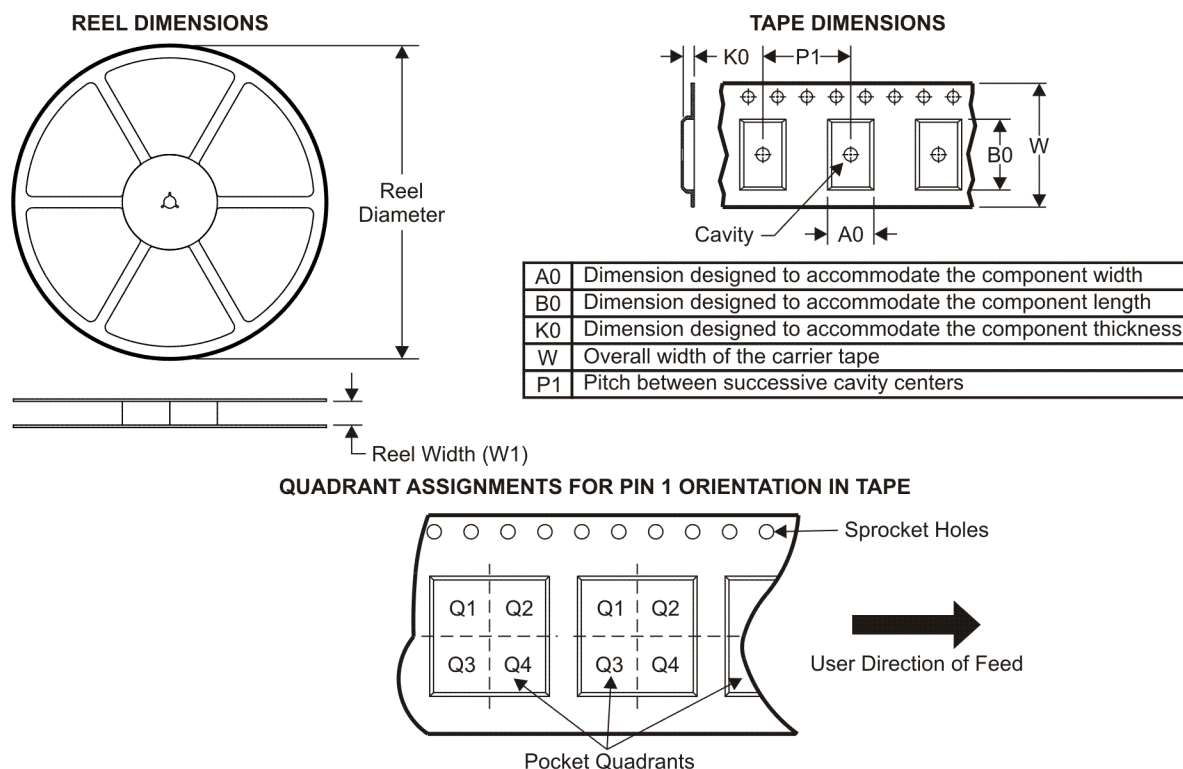
**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**TAPE AND REEL INFORMATION**


\*All dimensions are nominal

| Device       | Package Type | Package Drawing | Pins | SPQ  | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|--------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| TPS65021RHAR | VQFN         | RHA             | 40   | 2500 | 330.0              | 16.4               | 6.3     | 6.3     | 1.5     | 12.0    | 16.0   | Q2            |
| TPS65021RHAR | VQFN         | RHA             | 40   | 2500 | 330.0              | 16.4               | 6.3     | 6.3     | 1.5     | 12.0    | 16.0   | Q2            |
| TPS65021RHAT | VQFN         | RHA             | 40   | 250  | 330.0              | 16.4               | 6.3     | 6.3     | 1.5     | 12.0    | 16.0   | Q2            |
| TPS65021RHAT | VQFN         | RHA             | 40   | 250  | 180.0              | 16.4               | 6.3     | 6.3     | 1.5     | 12.0    | 16.0   | Q2            |

## TAPE AND REEL BOX DIMENSIONS

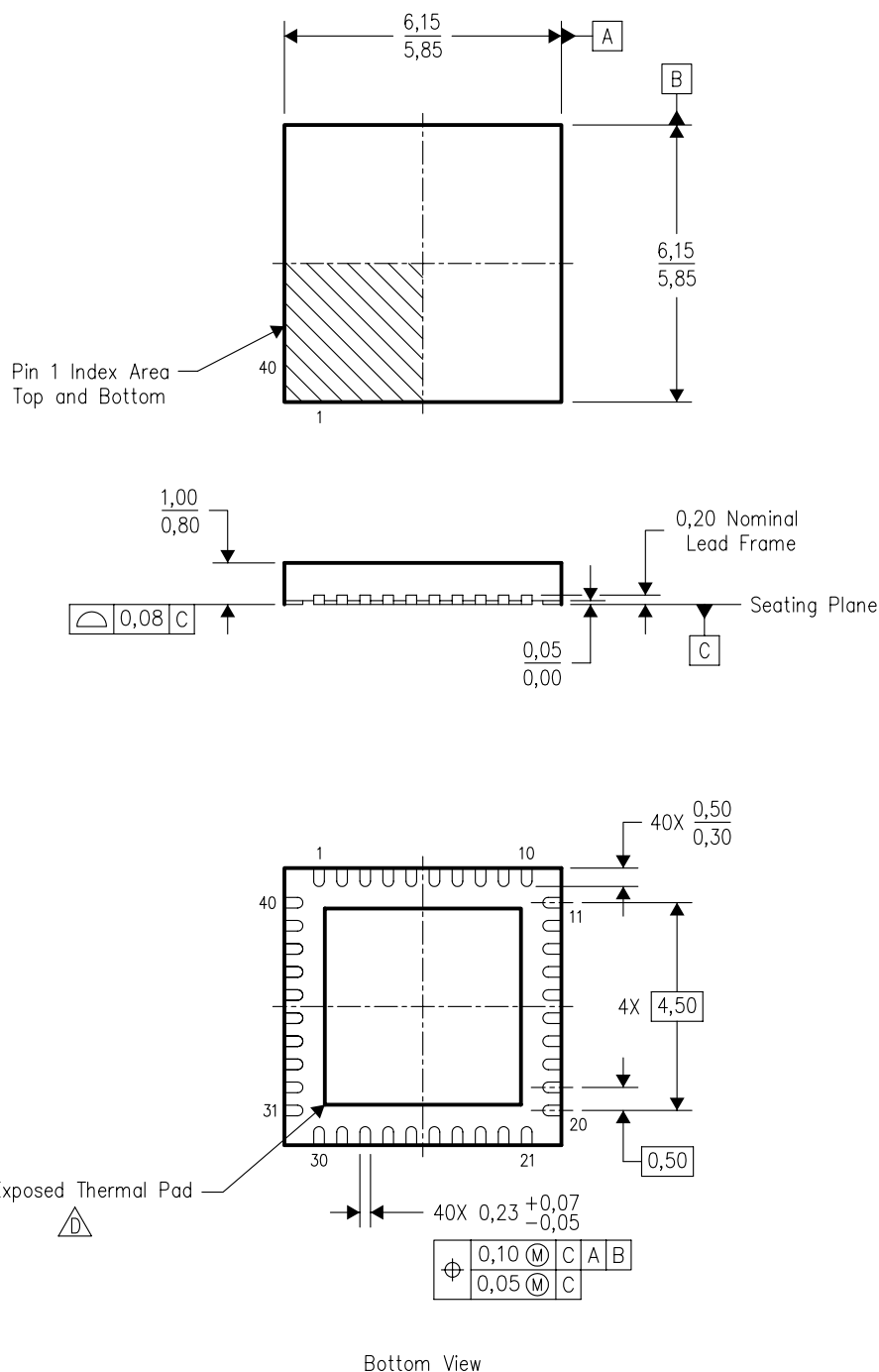


\*All dimensions are nominal

| Device       | Package Type | Package Drawing | Pins | SPQ  | Length (mm) | Width (mm) | Height (mm) |
|--------------|--------------|-----------------|------|------|-------------|------------|-------------|
| TPS65021RHAR | VQFN         | RHA             | 40   | 2500 | 346.0       | 346.0      | 33.0        |
| TPS65021RHAR | VQFN         | RHA             | 40   | 2500 | 333.2       | 345.9      | 28.6        |
| TPS65021RHAT | VQFN         | RHA             | 40   | 250  | 333.2       | 345.9      | 28.6        |
| TPS65021RHAT | VQFN         | RHA             | 40   | 250  | 190.5       | 212.7      | 31.8        |

RHA (S-PQFP-N40)

PLASTIC QUAD FLATPACK



Bottom View

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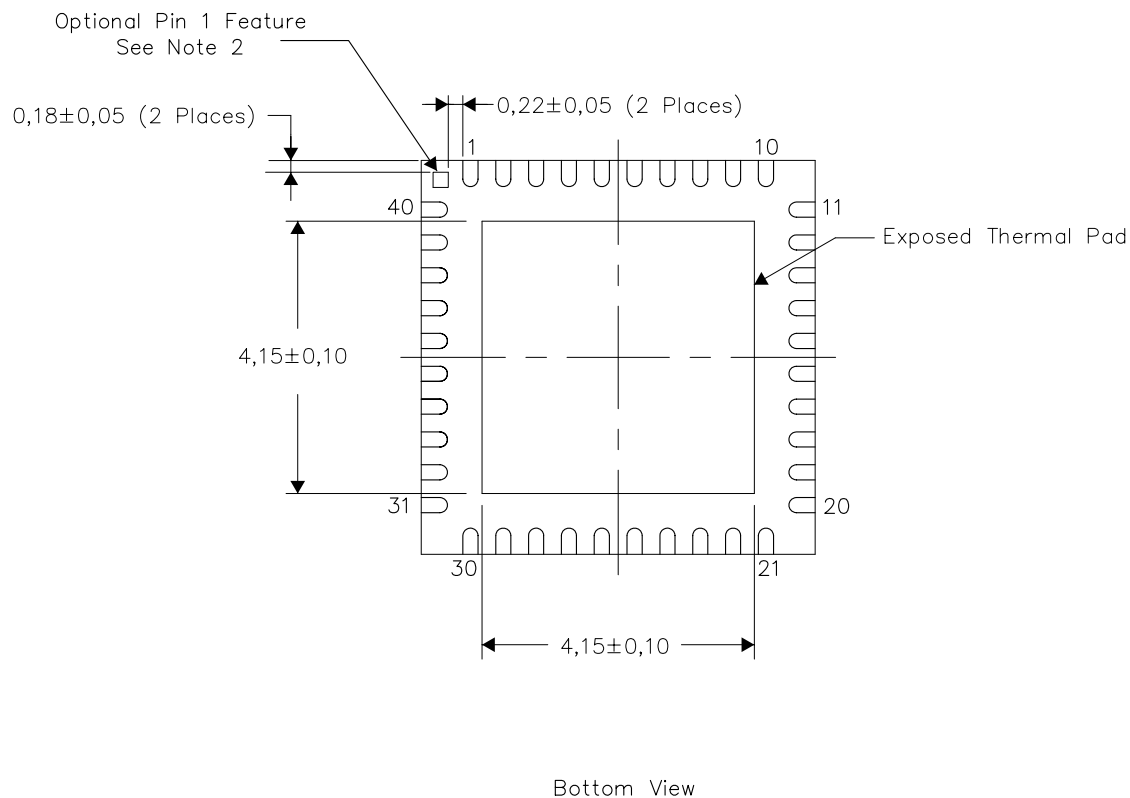
- NOTES:
- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - This drawing is subject to change without notice.
  - QFN (Quad Flatpack No-Lead) Package configuration.
  - The package thermal pad must be soldered to the board for thermal and mechanical performance. See the Product Data Sheet for details regarding the exposed thermal pad dimensions.
  - Package complies to JEDEC MO-220 variation VJJD-2.

## THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at [www.ti.com](http://www.ti.com).

The exposed thermal pad dimensions for this package are shown in the following illustration.

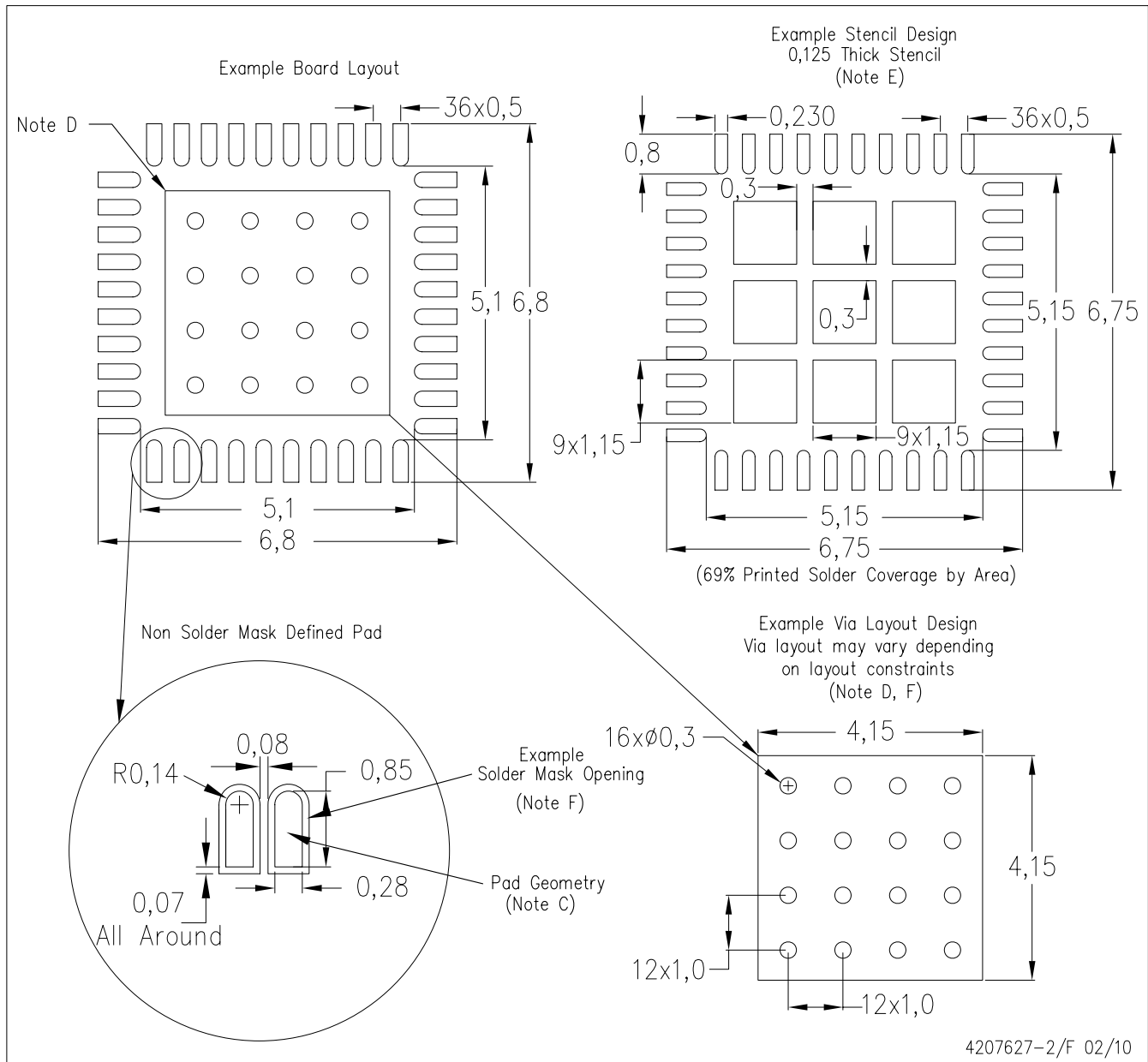


### NOTES:

- 1) All linear dimensions are in millimeters
- 2) The Pin 1 Identification mark is an optional feature that may be present on some devices  
In addition, this Pin 1 feature if present is electrically connected to the center thermal pad and therefore should be considered when routing the board layout.

## Exposed Thermal Pad Dimensions

RHA (S-PVQFN-N40)



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Publication IPC-7351 is recommended for alternate designs.
  - This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat-Pack Packages, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at [www.ti.com](http://www.ti.com) <<http://www.ti.com>>.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
  - Customers should contact their board fabrication site for recommended solder mask tolerances and via tenting recommendations for vias placed in the thermal pad.

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